



## MARKED-UP COPY OF SPECIFICATION

POWER MODEL FOR EMI SIMULATION ~~TO A SEMICONDUCTOR OF~~  
5 AN INTEGRATED CIRCUIT, METHOD OF DESIGNING THE POWER  
MODEL, EMI SIMULATOR, POWER MODEL PREPARATION  
COMPUTER PROGRAM, AND STORAGE MEDIUM STORING THE  
SAME AS WELL AS POWER MODEL DESIGN SUPPORT SYSTEM

### 10 BACKGROUND OF THE INVENTION

The present invention relates to a power model for an  
electro-magnetic interference simulation ~~to a semiconductor of an~~  
integrated circuit and a method of designing the power model as well as an  
15 electro-magnetic interference simulator having the power model, and a  
power model preparation computer program for generating the power  
model and a storage medium for storing the power model preparation  
computer program and further a power model design support system for  
designing the power model, and more particularly to a transistor description  
20 large scale integration power model for an electro-magnetic interference  
simulation ~~to a semiconductor of an~~ integrated circuit and a method of  
designing the transistor description large scale integration power model as  
well as an electro-magnetic interference simulator having the transistor  
description large scale integration power model, and a transistor description

large scale integration power model preparation computer program for  
generating the power model and a storage medium for storing the transistor  
description large scale integration power model preparation computer  
program and further a transistor description large scale integration power  
5 model design support system for designing the transistor description large  
scale integration power model.

The conventional techniques relative to the above are disclosed  
in the following four documents, for example, Nikkei Electronics 1998, 4-6,  
April 6, 1998, p. 143, 111, (hereinafter referred to as a first applicant's  
10 admitted prior art), and IEC TC93 New York Item Proposal, May 15, 1997  
entitled "Models of Integrated Circuits for EMI Behavioral Simulation"  
(hereinafter referred to as a second applicant's admitted prior art), and  
Japanese laid-open patent publication No. 10-54865 (hereinafter referred to  
as a third applicant's admitted prior art), and Japanese laid-open patent  
15 publication No. 11-120214 (hereinafter referred to as a fourth applicant's  
admitted prior art).

In order to suppress an electromagnetic radiation noise from  
being generated from electric, electronic and electron devices, it is effective  
to take certain countermeasures against the generation of the  
20 electromagnetic radiation noise in the design step. For this reason, a major  
~~of~~ circuit designers ~~introduced~~ have used an electro-magnetic interference  
simulator for their design work.

Actually, however, it often appears that the actually measured  
value does not correspond to the simulated value. One cause is that [[the]]

most of the simulators ~~does~~ do not analyze the power system of the circuit. An input/output buffer information specification (IBIS) model is one of the typical device models to be used in the electro-magnetic interference (EMI) simulator. The input/output buffer information specification (IBIS) model  
5 ~~are that~~ is the input buffer and the output buffer ~~are modeled~~ model. The electro-magnetic interference (EMI) simulator is based upon a simulation program with integrated circuit emphasis (SPICE) which is one of the circuit simulators, wherein models of the circuit elements are incorporated to calculate current values, so that a radiation electro-magnetic field is  
10 calculated from the current values.

The conventional electro-magnetic interference (EMI) simulation ~~modell~~ model for the large scale integrated circuit depends upon the signal-base analysis of the large scale integrated circuit ~~[[with]]~~, excluding power terminals and ground terminals from the circuit elements.

15 The power ~~of the~~ for a large scale integrated circuit is connected not only to the input/output buffers but also to internal circuits not directly relative to signal terminals, wherein ~~currents~~ current flowing through the internal circuits ~~include~~ includes high frequency components, for which reason it is undesirable to ignore the radiation electro-magnetic field due to  
20 the power current, that is a current flowing through a power terminal of a power terminal of an LSI (recall that current (amps) is power (watts) divided by voltage). In order to analyze the electro-magnetic interference (EMI) of ~~[[the]]~~ electric, electronic and electron devices, it is essential to analyze the power current of the printed board for analysis of the radiation

electro-magnetic field due to the power current.

In order to analyze the electro-magnetic interference (EMI) on the printed board, a model of the large scale integrated circuit mounted on the printed board is necessary in addition to a transmission ~~lines~~ line of the printed board. The format of the large scale integrated circuit model is classified into a transistor description format and an operational level description format. The transistor description format is that the internal circuit configurations of the large scale integrated circuit are accurately described with transistor models, interconnection resistance models and capacitance models. The transistor description format is generally used for designing the large scale integrated circuit. The operational level description format is that the transistor description format is simplified. The operational level description format is generally used for noise certification of the printed board. The above described input/output buffer information specification (IBIS) model is described in the operational level description format. The analysis of the radiation electromagnetic field from the power current will be described in the above two different formats.

The transistor description formation is used to find the power current for analysis of the radiation electromagnetic field. It is necessary to analyze the entire circuit ~~configurations~~ configuration of the large scale integrated circuit even when the circuit scale is tremendously large. FIG. 1 is a schematic view illustrative of an equivalent circuit of a conventional power model in the transistor description format for the electro-magnetic interference (EMI) simulation of the ~~semiconductor~~ integrated circuit. The

power model 38 in the transistor description format for the electro-magnetic interference (EMI) simulation of the semiconductor integrated circuit has a first power terminal 39, a second power terminal 40, and arrays of transistor blocks 40. A relatively small circuit scale, for example, a mask programmable read only memory needs about 5,000 transistors. A relatively large circuit scale, for example, a micro processor unit needs not less than about 1,000,000 transistors.

If, in accordance with the traditional signal-base analysis, the analysis only ~~[[to]]~~ of the signal terminals is made, it is possible that the circuit models of the large scale integrated circuit is simplified into the input/output buffers only. Notwithstanding, in accordance with the analysis in the transistor description format, it is impossible to omit the circuits because all of the circuits are connected directly or indirectly to the power terminals. For this reason, a total amount of calculations by the electro-magnetic interference (EMI) simulator is tremendously larger than the traditional signal-base analysis. This makes it difficult or impossible to conduct the analysis. Further, it is necessary for the user to receive the large scale integrated circuit model from the maker who manufactures the large scale integrated circuit. Notwithstanding, the transistor description format model includes ~~[[many]]~~ confidential ~~informations~~ information of the maker, for example, ~~informations~~ information about transistor structure, manufacturing processes, and internal circuit ~~con~~figurations configuration of the large scale integrated circuit. The maker usually hesitates to provide the user with the transistor description format model.

The following model was proposed for analysis of the radiation electromagnetic field in the operational level description format. FIG. 2 is a schematic view illustrative of an equivalent circuit of a conventional power model in the operational level description format for the electro-magnetic interference (EMI) simulation of the ~~semiconductor~~ integrated circuit, wherein the model comprises a current source and an impedance connected to the current source. A power model 42 for the electro-magnetic interference (EMI) simulation of the large scale integrated circuit has a first power terminal 39, a second power terminal 40, a current source 43 connected between the first and second power terminals 39 and 40, and an impedance 44 connected in parallel to the current source 43 and between the first and second power terminals 39 and 40, wherein the impedance 44 is connected across the current source 43. A display 45 displays a power current waveform from the current source, wherein a vertical axis represents an amplitude and a horizontal axis represents time. This method is, however, engaged with the following problems.

The internal impedance of the power terminal of the large scale integrated circuit varies depending upon inputs of signals and voltages of the power terminals. The variations in the internal impedance or resistance makes complicated current waveforms. In order to find a power current waveform of the power current, it is necessary to measure currents flowing from the power terminals in the actual circuit and convert the measured current values into the current waveform. The conversion method of converting the measured current values into the current waveform is not so

difficult because the analysis in a frequency region causes that as the frequency is constant, the impedance is also constant.

However, if the analysis is made in the time region, then the impedance varies over time and not constant, whereby the conversion  
5 method is very complicated. It is difficult to find the current waveform of the current source on the basis of the time region.

If the current waveform is actually measured for finding the current waveform of the large scale integrated circuit, the current waveform includes ~~informations~~ information about impedance of the DC power  
10 circuit. The impedance in the circuit is also present in the model, for which reason the effect of the impedance is doubly considered, whereby the obtainable current waveform is made inaccurate.

If in order to find the accurate current value of the power terminal, the simulation is made in accordance with the transistor  
15 description format model, then the above described problems are also raised.

In ~~summery to the above descriptions~~ summary, the first problem is that the conventional transistor description format large scale integrated circuit model is incapable of or ~~is hard to~~ has difficulty simulating the  
20 electro-magnetic interference (EMI) ~~simulation to~~ of the power system of the large scale integrated circuit, because the circuit scale of the large scale integrated circuit is tremendously large and it is difficult to omit the circuits for conducting the simulation as the analysis to the signal terminals.

The second problem is that the operational level description

format large scale integrated circuit model is very hard to conduct the electro-magnetic interference (EMI) simulation in the time region, because the internal impedance of the large scale integrated circuit varies over time or in the time region, whereby it is extremely difficult to represent the  
5 current waveform of the power source of the operational level description format large scale integrated circuit model.

The third problem is that the conventional electro-magnetic interference (EMI) simulation conducts the analysis in the inaccurate state, because as the large scale integrated circuit is in the actual operation state,  
10 only parts of the large scale integrated circuit are operated. Namely, the analysis is made depending upon the actually operated parts of the large scale integrated circuit but not entire of the circuit.

In the above circumstances, it had been required to develop a novel invention free from the above problem.  
15

## SUMMARY OF THE INVENTION

Accordingly, it is an object of the present invention to provide a novel power model for an electro-magnetic interference simulation to a  
20 ~~semiconductor~~ an integrated circuit free from the above problems.

It is a further object of the present invention to provide a novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model allows an extremely accurate electro-magnetic interference simulation from a power



system of a printed board.

It is a still further object of the present invention to provide a novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model makes it  
5 easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is yet a further object of the present invention to provide a novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed  
10 on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is a ~~further more~~ furthermore object of the present invention to  
15 provide a novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a  
20 power system of a printed board.

It is moreover an object of the present invention to provide a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit free from the above problems.

It is still more an object of the present invention to provide a novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the method allows an extremely accurate electro-magnetic interference  
5 simulation from a power system of a printed board.

It is yet more an object of the present invention to provide a novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the method makes it easy to conduct an extremely accurate  
10 electro-magnetic interference simulation from a power system of a printed board.

It is still ~~further more~~ furthermore an object of the present invention to provide a novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
15 circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is yet ~~further more~~ furthermore an object of the present  
20 invention to provide a novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic

interference simulation from a power system of a printed board.

It is another object of the present invention to provide a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
5 circuit free from the above problems.

It is further another object of the present invention to provide a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the electro-magnetic interference simulator allows an  
10 extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is still another object of the present invention to provide a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
15 circuit, wherein the electro-magnetic interference simulator makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is yet another object of the present invention to provide a novel electro-magnetic interference simulator using a power model for an  
20 electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is more another object of the present invention to provide a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all  
5 ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is a still further another object of the present invention to provide a novel power model preparation computer program for preparing  
10 a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit free from the above problems.

It is a yet further another object of the present invention to provide a novel power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to a  
15 ~~semiconductor~~ an integrated circuit, wherein the power model preparation computer program allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is furthermore another object of the present invention to provide a novel power model preparation computer program for preparing  
20 a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model preparation computer program makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is moreover another object of the present invention to provide a novel power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of  
5 all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is still moreover another object of the present invention to provide a novel power model preparation computer program for preparing  
10 a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a  
15 printed board.

It is an additional object of the present invention to provide a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit free from the above  
20 problems.

It is a further additional object of the present invention to provide a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power

model preparation computer program allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

5 It is a still further additional object of the present invention to provide a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model preparation computer program makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a  
10 power system of a printed board.

It is yet a further additional object of the present invention to provide a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein  
15 the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is a ~~further more~~ furthermore additional object of the present  
20 invention to provide a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the

circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is also an additional object of the present invention to provide a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to a  
5 ~~semiconductor~~ an integrated circuit free from the above problems.

It is also an additional object of the present invention to provide a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to a  
10 ~~semiconductor~~ an integrated circuit, wherein the power model allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is also an additional object of the present invention to provide a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to a  
15 ~~semiconductor~~ an integrated circuit, wherein the power model makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

It is also an additional object of the present invention to provide a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to a  
20 ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate

electro-magnetic interference simulation from a power system of a printed board.

It is also an additional object of the present invention to provide a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to a  
5 power model for an electro-magnetic interference simulation to a semiconductor ~~an~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a  
10 printed board.

The novel electro-magnetic interference (EMI) simulation model in accordance with the present invention is represented in the transistor description format for conducting the simulation to the radiation electro-magnetic field generated on the printed board. This transistor  
15 description format large scale integrated circuit power model is largely reduced in the number of transistors constituting this model. The electro-magnetic interference (EMI) simulator utilizes this transistor description format large scale integrated circuit power model to find a power current which flows on an interconnection of a printed board. This  
20 transistor description format large scale integrated circuit power model is prepared by extracting operating parts from a net-list for the large scale integrated circuit to reduce the number of transistors constituting this model. Non-operating parts of the large scale integrated circuit are simplified to be incorporated into the model. Namely, the transistor



description format large scale integrated circuit power model includes the operating parts extracted from the net-list and the simplified non-operating parts, so that all of the parts of the large scale integrated circuit are utilized to prepare the transistor description format large scale integrated circuit  
5 power model.

The above and other objects, features and advantages of the present invention will be apparent from the following descriptions.

### BRIEF DESCRIPTION OF THE DRAWINGS

Preferred embodiments according to the present invention will be  
10 described in detail with reference to the accompanying drawings.

FIG. 1 is a schematic view illustrative of an equivalent circuit of a conventional power model in the transistor description format for the electro-magnetic interference (EMI) simulation of the ~~semiconductor~~  
integrated circuit.

15 FIG. 2 is a schematic view illustrative of an equivalent circuit of a conventional power model in the operational level description format for the electro-magnetic interference (EMI) simulation of the ~~semiconductor~~  
integrated circuit.

FIG. 3 is a circuit diagram illustrative of a first novel power  
20 model for an electro-magnetic interference simulation to a ~~semiconductor~~  
an integrated circuit in a first embodiment in accordance with the present invention.

FIG. 4 is a circuit diagram illustrative of a second novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~

an integrated circuit in a second embodiment in accordance with the present invention.

FIG. 5 is a circuit diagram illustrative of a third novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~  
5 an integrated circuit in a third embodiment in accordance with the present invention.

FIG. 6 is a circuit diagram illustrative of a fourth novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~  
an integrated circuit in a fourth embodiment in accordance with the present  
10 invention.

FIG. 7 is a circuit diagram illustrative of a fifth novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~  
an integrated circuit in a fifth embodiment in accordance with the present invention.

15 FIG. 8 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a first novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a sixth  
20 embodiment in accordance with the present invention.

FIG. 9 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in the first novel method of designing a power model for an electro-magnetic

interference simulation to ~~a semiconductor~~ an integrated circuit in a seventh embodiment in accordance with the present invention.

FIG. 10 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a second novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in an eighth embodiment in accordance with the present invention.

FIG. 11 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a second novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a ninth embodiment in accordance with the present invention.

FIG. 12 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a third novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a tenth embodiment in accordance with the present invention.

FIG. 13 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a third novel method of designing a power model for an

electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in an eleventh embodiment in accordance with the present invention.

FIG. 14 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a fourth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a twelfth embodiment in accordance with the present invention.

FIG. 15 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a fourth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a thirteenth embodiment in accordance with the present invention.

FIG. 16 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a fifth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a fourteenth embodiment in accordance with the present invention.

FIG. 17 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two stage gate circuits, wherein the novel processes are involved in a fifth novel method of designing a power model for an

electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a fifteenth embodiment in accordance with the present invention.

FIG. 18 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the first novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a sixteenth embodiment in accordance with the present invention.

FIG. 19 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the second novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a seventeenth embodiment in accordance with the present invention.

FIG. 20 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the third novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in an eighteenth embodiment in accordance with the present invention.

FIG. 21 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the fourth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a nineteenth embodiment in accordance with the present invention.

FIG. 22 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the fifth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a twentieth embodiment in accordance with the present invention.

FIG. 23 is a block diagram illustrative of a support system for designing a power model in a twenty first embodiment according to the present invention.

FIG. 24 is a flow chart illustrative of the electromagnetic interference simulation to the ~~semiconductor~~ integrated circuit by use of a simulator on the basis of the first and second novel power models shown in FIGS. 3 and 4 and prepared by the first, second, third, fourth and fifth design methods executed by the supporting system shown in FIG. 23.

FIG. 25 is a circuit diagram illustrative of a modeled circuit board connected to the novel power model for the electromagnetic

interference simulation in accordance with the present invention.

FIG. 26 is a circuit diagram illustrative of a modeled ~~semiconductor~~ integrated circuit for the electromagnetic interference simulation in accordance with the present invention.

5           FIG. 27 is a diagram illustrative of variations in currents over frequency to show frequency spectrums which has been transformed by Fourier-transform from a current waveform which represents variation in current over time at a fixed point of a circuit board, wherein ● represents an actually measured value, ~~whilst~~ while ○ represents an analyzed value.

10

#### DISCLOSURE OF THE INVENTION

The novel electro-magnetic interference (EMI) simulation model in accordance with the present invention is represented in the transistor description format for conducting the simulation to the radiation  
15   electro-magnetic field generated on the printed board. This transistor description format large scale integrated circuit power model is largely reduced in the number of transistors constituting this model. The electro-magnetic interference (EMI) simulator utilizes this transistor description format large scale integrated circuit power model to find a  
20   power current which flows on an interconnection of a printed board. This transistor description format large scale integrated circuit power model is prepared by extracting operating parts from a net-list for the large scale integrated circuit to reduce the number of transistors constituting this model. Non-operating parts of the large scale integrated circuit are

simplified to be incorporated into the model. Namely, the transistor description format large scale integrated circuit power model includes the operating parts extracted from the net-list and the simplified non-operating parts, so that all of the parts of the large scale integrated circuit are utilized  
5 to prepare the transistor description format large scale integrated circuit power model.

In accordance with the present invention, the power system of the large scale integrated circuit is modeled into an inverter circuit and an equivalent ~~capacity~~ capacitor. As compared to the conventional transistor  
10 description format large scale integrated circuit power model, a calculation load to the electro-magnetic interference (EMI) simulator is reduced, thereby making it easy to conduct the power current analysis. The non-operating parts of the large scale integrated circuit are considered on the electro-magnetic interference (EMI) simulation, whereby the large scale  
15 integrated circuit model shows similar ~~operations~~ operation or ~~behaviors~~ behavior to the actual ~~operations~~ operation or ~~behaviors~~ behavior of the actual large scale integrated circuit. This makes it possible to find a highly accurate power current of the large scale integrated circuit. Since the confidential detailed ~~informations~~ information about the internal circuit  
20 configurations of the large scale integrated circuit and the device structures are not included in this transistor description format large scale integrated circuit power model, the maker who manufactures the large scale integrated circuit is likely to show this transistor description format large scale integrated circuit power model to the user with keeping the detailed



~~informations~~ information to be confidential.

The first present invention provides a power model for a ~~semiconductor~~ an integrated circuit, wherein the power model comprises a logic gate circuit part representing an operating part of the ~~semiconductor~~ integrated circuit and an equivalent internal capacitive part representing a non-operating part of the ~~semiconductor~~ integrated circuit.

It is also preferable that the power model is independently provided for each of plural power systems which are independent from each other and included in the ~~semiconductor~~ integrated circuit.

It is also preferable that internal circuit configurations of the ~~semiconductor~~ integrated circuit are divided into plural blocks on the basis of arrangement ~~informations~~ information, and the power model is provided for each of the plural blocks.

It is also preferable that internal circuit configurations of the ~~semiconductor~~ integrated circuit are divided into plural groups, each of the plural groups comprises a same timing group which includes logic gate circuits having individual signal transmission delay times fallen in a group-belonging predetermined time range which belongs to each of the plural groups, and the power model is provided for each of the plural groups.

It is also preferable that the power model further comprises a signal source connected to the logic gate circuit part for supplying a frequency-fixed signal to the logic gate circuit part, so that the logic gate circuit part represents operating state parts of the ~~semiconductor~~ integrated

circuit in accordance with the frequency-fixed signal, and the equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuit.

5 It is also preferable that the equivalent internal capacitive part further represents operating-irrelevant fixed parts of the ~~semiconductor~~ integrated circuit.

It is also preferable that the logic gate circuit part is connected between first and second ~~powers~~ power terminals, and the equivalent internal capacitive part is also connected between the first and second  
10 ~~powers~~ power terminals.

It is also preferable that the logic gate circuit part further comprises a single pair of an inverter circuit and a load capacitive element, and the inverter circuit is connected between the first and second ~~powers~~ power terminals and the load capacitive element is also connected between  
15 the first and second ~~powers~~ power terminals, and the load capacitive element is placed between the inverter circuit and the equivalent internal capacitive part.

It is also preferable that the load capacitive element comprises a series connection of a first load capacitance and a second load capacitance  
20 between the first and second ~~powers~~ power terminals, and an intermediate point between the first and second load capacitances is connected to an output terminal of the inverter circuit.

It is also preferable that the equivalent internal capacitive part further comprises at least an equivalent internal capacitive element

connected between the first and second ~~powers~~ power terminals.

It is also preferable that a plurality of the equivalent internal capacitive element is connected between the first and second ~~powers~~ power terminals, and the equivalent internal capacitive element comprises a series  
5 connection of a capacitance and a resistance between the first and second ~~powers~~ power terminals.

It is also preferable that the inverter circuit comprises a series connection of a p-channel MOS field effect transistor and an n-channel MOS field effect transistor, and gate electrodes of the p-channel and  
10 n-channel MOS field effect transistors are connected to a clock signal source for applying a clock signal to the gate electrodes of the p-channel and n-channel MOS field effect transistors.

It is also preferable that the logic gate circuit part further comprises plural pairs of an inverter circuit and a load capacitive element,  
15 and the inverter circuit is connected between the first and second ~~powers~~ power terminals and the load capacitive element is also connected between the first and second ~~powers~~ power terminals, and in each pair, the load capacitive element is placed closer to the equivalent internal capacitive part than the inverter circuit.

20 It is also preferable that the load capacitive element comprises a series connection of a first load capacitance and a second load capacitance between the first and second ~~powers~~ power terminals, and an intermediate point between the first and second load capacitances is connected to an output terminal of the inverter circuit.

It is also preferable that the equivalent internal capacitive part further comprises at least an equivalent internal capacitive element connected between the first and second ~~powers~~ power terminals.

5 It is also preferable that a plurality of the equivalent internal capacitive element is connected between the first and second ~~powers~~ power terminals, and the equivalent internal capacitive element comprises a series connection of a capacitance and a resistance between the first and second ~~powers~~ power terminals.

10 It is also preferable that the inverter circuit comprises a series connection of a p-channel MOS field effect transistor and an n-channel MOS field effect transistor, and gate electrodes of the p-channel and n-channel MOS field effect transistors are connected to a clock signal source for applying a clock signal to the gate electrodes of the p-channel and n-channel MOS field effect transistors.

15 It is also preferable that the equivalent internal capacitive part is placed between the logic gate circuit part and a power system side.

It is also preferable that the power model is ~~deigned~~ designed for simulation to a current distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

20 It is also preferable that the power model is ~~deigned~~ designed for an electro-magnetic interference simulation to an electromagnetic field distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

The second present invention provides a method of designing a power model for a ~~semiconductor~~ an integrated circuit. The power model comprises a logic gate circuit part and an equivalent internal capacitive part, wherein operating-related ~~informations~~ information of all gate circuits  
5 constituting the ~~semiconductor~~ integrated circuit are utilized in first sequential processes to prepare the logic gate circuit part of the power model, and wherein non-operating-related ~~informations~~ information of the all gate circuits constituting the ~~semiconductor~~ integrated circuit are utilized in second sequential processes separated from the first sequential  
10 processes to prepare the equivalent internal capacitive part of the power model.

It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of operating-state p-channel transistors in the operating-state of the constituting gate circuits are utilized  
15 to decide a gate width of a model p-channel transistor; ~~informations~~ information about gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits are utilized to decide a gate width of a model n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the operating-state p-channel transistors in the  
20 operating-state of the constituting gate circuits and about interconnection capacitances between the operating-state p-channel transistors and a first power are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the operating-state n-channel transistors in the operating-state of the

constituting gate circuits and about interconnection capacitances between the operating-state n-channel transistors and a second power terminal are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel  
5 transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a sum of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel  
10 transistor; a sum of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a sum of gate capacitances of the operating-state p-channel transistors and interconnection capacitances between the operating-state p-channel transistors and the first power  
15 terminal is defined to be a model first load ~~capacity~~ capacitor; and a sum of gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a  
20 single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a sum of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel

transistor; a half of a sum of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a sum of gate capacitances of the operating-state p-channel transistors and  
5 interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a sum of gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power  
10 terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the  
15 operating-state gate circuits and an ~~averaged~~ average value of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of operating-state n-channel  
20 transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state p-channel transistors and a second ~~averaged~~ average value of interconnection

capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state  
5 n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first  
10 and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel  
15 transistor; a half of a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the operating-state gate circuits and a sum of both  
20 a first ~~averaged~~ average value of gate capacitances of the operating-state p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the number of the



operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state n-channel transistors and the second power terminal is  
5 defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the first sequential processes,  
10 ~~informations~~ information about gate widths of all p-channel transistors of the constituting gate circuits and an information about operational rate of operating-state p-channel transistors in the operating-state are utilized to decide a gate width of a model p-channel transistor; ~~informations~~  
information about gate widths of all n-channel transistors of the  
15 constituting gate circuits and an information about operational rate of operating-state n-channel transistors in the operating-state are utilized to decide a gate width of a model n-channel transistor; ~~informations~~  
information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information  
20 about interconnection capacitances between the all p-channel transistors and a first power terminal and ~~informations~~ information about the operational rate are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~

information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about the operational rate are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of  
5 p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the  
10 constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of  
15 the number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, an average  
20 operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a

model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the  
5 all gate circuits, an average operational rate of the gate circuits, and an  
~~averaged~~ average value of gate widths of the all p-channel transistors in the  
all of the constituting gate circuits is defined to be a gate width of a model  
p-channel transistor; a half of a product of the number of the all gate  
circuits, an average operational rate of the gate circuits, and an ~~averaged~~  
10 average value of gate widths of all n-channel transistors in the all of the  
constituting gate circuits is defined to be a gate width of a model n-channel  
transistor; a half of a product of the number of the all gate circuits, an  
average operational rate of the gate circuits, and a sum of both a first  
~~averaged~~ average value of gate capacitances of the all p-channel transistors  
15 and a second ~~averaged~~ average value of interconnection capacitances  
between the all p-channel transistors and the first power terminal is defined  
to be a model first load ~~capacity~~ capacitor; and a half of a product of the  
number of the all gate circuits, an average operational rate of the gate  
circuits, and a sum of both a first ~~averaged~~ average value of gate  
20 capacitances of the all n-channel transistors and a second ~~averaged~~ average  
value of interconnection capacitances between the all n-channel transistors  
and the second power terminal is defined to be a model second load  
~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs  
of p-channel and n-channel transistors and two pairs of first and second

load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, a maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the all gate circuits, a maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model

5 p-channel transistor; a half of a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate circuits, the

10 maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the

15 number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors

20 and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of all p-channel transistors of

the constituting gate circuits and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model p-channel transistor; ~~informations~~ information about gate widths of all n-channel transistors of the constituting gate circuits and

5 ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between

10 the all p-channel transistors and a first power terminal and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~

15 information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors

20 and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, and a power current ratio of an ~~averaged~~ average current value of the basic gate circuits to an ~~averaged~~ average current value of the constituting gate circuits, and an ~~averaged~~ average value of gate widths of

the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, the power current ratio, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the

5 constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the

10 first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the

15 second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the

20 all gate circuits, and a power current ratio of an ~~averaged~~ average current value of the basic gate circuits to an ~~averaged~~ average current value of the constituting gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a

product of the number of the all gate circuits, the power current ratio, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the second sequential processes, ~~informations~~ information about ON-resistances of non-operating-state transistors in the non-operating-state of the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits and about interconnection capacitances between the operating-state transistors and a power are utilized to decide the



equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a reciprocal of a sum of reciprocals of ON-resistances of non-operating p-channel transistors in the non-operating state is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a reciprocal of a sum of reciprocals of ON-resistances of non-operating n-channel transistors in the non-operating state is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; an arithmetic mean of a sum of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and a sum of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and an arithmetic mean of a sum of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and a sum of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal

~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that in the second sequential processes, ~~informations~~ information about an ~~averaged~~ average value of ON-resistances of all transistors included in the constituting gate circuits and the number of non-operating gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating-state transistors in the

non-operating-state of the constituting gate circuits, and the number of non-operating gate circuits as well as ~~informations~~ information about an ~~averaged~~ average value of interconnection capacitances between the operating-state transistors and a power are utilized to decide the equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of a total number of the constituting logic gate included in the ~~semiconductor~~ integrated circuit and a remainder by subtracting an average operational rate from 1; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and

an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined  
5 to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of a total number of the  
10 constituting logic gate included in the ~~semiconductor~~ integrated circuit and a remainder by subtracting a maximum operational rate from 1; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of  
15 a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the  
20 non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~

capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate capacities capacitances of the non-operating n-channel transistors and an averaged average value of interconnection capacities capacitances between the  
5 non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal capacity capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal capacity capacitor is designed.

It is also preferable that informations information about an  
10 averaged average value of ON-resistances of all transistors included in the constituting gate circuits and informations information about currents of basic gate circuits and the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal capacity capacitor; and informations information about an averaged average value of gate  
15 capacities capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits, and informations information about currents of basic gate circuits and the constituting gate circuits as well as informations information about an averaged average value of interconnection capacitances between the operating-state  
20 transistors and a power are utilized to decide the equivalent internal capacity capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal capacity capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of the total number of

the constituting gate circuits included in the ~~semiconductor~~ integrated circuit and a power current ratio which is defined to be a ratio of an averaged average current value of all of basic gate circuits to an averaged average current value of all of the constituting gate circuits; a double of a product of an averaged average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal capacity capacitor; a double of a product of an averaged average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal capacity capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate capacities capacitances of the non-operating p-channel transistors and an averaged average value of interconnection capacities capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal capacity capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate capacities capacitances of the non-operating n-channel transistors and an averaged average value of interconnection capacities capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal capacity capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent

internal ~~capacity~~ capacitor is designed.

It is also preferable that the equivalent internal capacitive part is placed between the logic gate circuit part and a power system side.

It is also preferable that the power model is ~~deigned~~ designed for  
5 simulation to a current distribution over a circuit board on which the  
~~semiconductor~~ integrated circuit is mounted.

It is also preferable that the power model is ~~deigned~~ designed for  
an electro-magnetic interference simulation to an electromagnetic field  
distribution over a circuit board on which the ~~semiconductor~~ integrated  
10 circuit is mounted.

The third present invention provides a storage medium for  
storing a computer program for designing a power model for a  
~~semiconductor~~ an integrated circuit, and the power model comprises a logic  
gate circuit part and an equivalent internal capacitive part, wherein  
15 operating-related ~~informations~~ information of all gate circuits constituting  
the ~~semiconductor~~ integrated circuit are utilized in first sequential  
processes to prepare the logic gate circuit part of the power model, and  
wherein non-operating-related ~~informations~~ information of the all gate  
circuits constituting the ~~semiconductor~~ integrated circuit are utilized in  
20 second sequential processes separated from the first sequential processes to  
prepare the equivalent internal capacitive part of the power model.

It is also preferable that in the first sequential processes,  
~~informations~~ information about gate widths of operating-state p-channel  
transistors in the operating-state of the constituting gate circuits are utilized

to decide a gate width of a model p-channel transistor; ~~informations~~  
information about gate widths of operating-state n-channel transistors in the  
operating-state of the constituting gate circuits are utilized to decide a gate  
width of a model n-channel transistor; ~~informations~~ information about gate  
5 ~~capacities~~ capacitances of the operating-state p-channel transistors in the  
operating-state of the constituting gate circuits and about interconnection  
capacitances between the operating-state p-channel transistors and a first  
power terminal are utilized to decide a model first load ~~capacity~~ capacitor;  
and ~~informations~~ information about gate ~~capacities~~ capacitances of the  
10 operating-state n-channel transistors in the operating-state of the  
constituting gate circuits and about interconnection capacitances between  
the operating-state n-channel transistors and a second power terminal are  
utilized to decide a model second load ~~capacity~~ capacitor, whereby the  
logic gate circuit part comprising at least a pair of p-channel and n-channel  
15 transistors and at least a pair of first and second load ~~capacities~~ capacitors  
is designed.

It is also preferable that a sum of gate widths of the  
operating-state p-channel transistors in the operating-state of the  
constituting gate circuits is defined to be a gate width of a model p-channel  
20 transistor; a sum of gate widths of operating-state n-channel transistors in  
the operating-state of the constituting gate circuits is defined to be a gate  
width of a model n-channel transistor; a sum of gate capacitances of the  
operating-state p-channel transistors and interconnection capacitances  
between the operating-state p-channel transistors and the first power



terminal is defined to be a model first load ~~capacit~~ capacity capacitor; and a sum of gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second  
5 load ~~capacit~~ capacity capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a sum of gate widths of the operating-state p-channel transistors in the operating-state of the  
10 constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a sum of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a sum of gate capacitances of the operating-state p-channel transistors and  
15 interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacit~~ capacity capacitor; and a half of a sum of gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power  
20 terminal is defined to be a model second load ~~capacit~~ capacity capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of the operating-state p-channel transistors in the operating-state of the

constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits

5 is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state p-channel

10 transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the number of the operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the

15 operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

20 It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of all p-channel transistors of the constituting gate circuits and ~~[[an]]~~ information about operational rate of operating-state p-channel transistors in the operating-state are utilized to decide a gate width of a model p-channel transistor; ~~informations~~

information about gate widths of all n-channel transistors of the constituting gate circuits and ~~[[an]]~~ information about operational rate of operating-state n-channel transistors in the operating-state are utilized to decide a gate width of a model n-channel transistor; ~~informations~~  
5 information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all p-channel transistors and a first power terminal and ~~informations~~ information about the operational rate are utilized to decide a model first load ~~capacity~~ capacitor;  
10 and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about the operational rate are utilized to decide a model second load ~~capacity~~  
15 capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~  
20 average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits

is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first

averaged average value of gate capacitances of the all p-channel transistors and a second averaged average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the  
5 number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first averaged average value of gate capacitances of the all n-channel transistors and a second averaged average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load  
10 ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, a maximum operational rate of the gate circuits, and an averaged  
15 average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and an averaged average value of gate widths of all n-channel transistors in the all of the constituting gate circuits  
20 is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first averaged average value of gate capacitances of the all p-channel transistors and a second averaged average value of interconnection capacitances between the all p-channel transistors

and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors  
5 and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is  
10 designed.

It is also preferable that a half of a product of the number of the all gate circuits, a maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model  
15 p-channel transistor; a half of a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate circuits, the  
20 maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the

number of the all gate circuits, the maximum operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors  
5 and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the first sequential processes,  
10 ~~informations~~ information about gate widths of all p-channel transistors of the constituting gate circuits and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model p-channel transistor; ~~informations~~ information about gate widths of all n-channel transistors of the constituting gate circuits and  
15 ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between  
20 the all p-channel transistors and a first power terminal and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~



information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, and a power current ratio of an ~~averaged~~ average current value of the basic gate circuits to an ~~averaged~~ average current value of the constituting gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, the power current ratio, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the

second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

5           It is also preferable that a half of a product of the number of the all gate circuits, and a power current ratio of an ~~averaged~~ average current value of the basic gate circuits to an ~~averaged~~ average current value of the constituting gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is  
10 defined to be a gate width of a model p-channel transistor; a half of a product of the number of the all gate circuits, the power current ratio, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate  
15 circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model  
-first load ~~capacity~~ capacitor; and a half of a product of the number of the all  
20 gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part

comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the second sequential processes, ~~informations~~ information about ON-resistances of non-operating-state  
5 transistors in the non-operating-state of the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits and about interconnection capacitances between  
10 the operating-state transistors and a power are utilized to decide the equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a reciprocal of a sum of  
15 reciprocals of ON-resistances of non-operating p-channel transistors in the non-operating state is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a reciprocal of a sum of reciprocals of ON-resistances of non-operating n-channel transistors in the non-operating state is defined to be an ON-resistance of a second  
20 equivalent internal ~~capacity~~ capacitor; an arithmetic mean of a sum of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and a sum of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and an arithmetic mean of a sum of

gate ~~capacities~~ capacitances of the non-operating n-channel transistors and a sum of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal  
5 capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a product of an averaged average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating  
10 gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an averaged average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor;  
15 capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an averaged average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to  
20 be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an averaged average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors

and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that in the second sequential processes,  
5 ~~informations~~ information about an ~~averaged~~ average value of ON-resistances of all transistors included in the constituting gate circuits and the number of non-operating gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and  
~~informations~~ information about an ~~averaged~~ average value of gate  
10 ~~capacities~~ capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits, and the number of non-operating gate circuits as well as ~~informations~~ information about an ~~averaged~~ average value of interconnection capacitances between the operating-state transistors and a power are utilized to decide the equivalent  
15 internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of a total number of the constituting logic gate included in the ~~semiconductor~~ integrated circuit and  
20 a remainder by subtracting an average operational rate from 1; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an

averaged average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an averaged average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an averaged average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an averaged average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of a total number of the constituting logic gate included in the ~~semiconductor~~ integrated circuit and a remainder by subtracting a maximum operational rate from 1; a double of a product of an averaged average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of

a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second  
5 equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first  
10 power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the  
15 non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that ~~informations~~ information about an  
20 ~~averaged~~ average value of ON-resistances of all transistors included in the constituting gate circuits and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about an ~~averaged~~ average value of gate

~~capacities~~ capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits, and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits as well as ~~informations~~ information about an ~~averaged~~ average value of interconnection capacitances between the operating-state transistors and a power are utilized to decide the equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of the total number of the constituting gate circuits included in the ~~semiconductor~~ integrated circuit and a power current ratio which is defined to be a ratio of an ~~averaged~~ average current value of all of basic gate circuits to an ~~averaged~~ average current value of all of the constituting gate circuits; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel



transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and  
5 an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the  
10 equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the equivalent internal capacitive part is placed between the logic gate circuit part and a power system side.

It is also preferable that the power model is ~~deigned~~ designed for  
15 simulation to a current distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

It is also preferable that the power model is ~~deigned~~ designed for  
an electro-magnetic interference simulation to an electromagnetic field distribution over a circuit board on which the ~~semiconductor~~ integrated  
20 circuit is mounted.

The fourth present invention provides a supporting system for designing a power model for a ~~semiconductor~~ an integrated circuit, and ~~The~~ the power model comprises a logic gate circuit part and an equivalent internal capacitive part. The supporting system comprises: a data base

storing ~~informations~~ information of internal circuit configurations; a storage medium for storing ~~informations~~ information about circuit elements and interconnections between the circuit elements of the power model as well as for storing a computer program for designing the power model; a  
5 processor being connected to the data base and the storage medium for executing the computer program to prepare the power model; and an output device being connected to the processor for outputting the power model prepared by the processor, wherein operating-related ~~informations~~ information of all gate circuits constituting the ~~semiconductor~~ integrated  
10 circuit are utilized in first sequential processes to prepare the logic gate circuit part of the power model, and wherein non-operating-related ~~informations~~ information of the all gate circuits constituting the ~~semiconductor~~ integrated circuit are utilized in second sequential processes separated from the first sequential processes to prepare the equivalent  
15 internal capacitive part of the power model.

It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of operating-state p-channel transistors in the operating-state of the constituting gate circuits are utilized to decide a gate width of a model p-channel transistor; ~~informations~~  
20 information about gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits are utilized to decide a gate width of a model n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the operating-state p-channel transistors in the operating-state of the constituting gate circuits and about interconnection

capacitances between the operating-state p-channel transistors and a first power terminal are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the operating-state n-channel transistors in the operating-state of the

5 constituting gate circuits and about interconnection capacitances between the operating-state n-channel transistors and a second power terminal are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors

10 is designed.

It is also preferable that a sum of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a sum of gate widths of operating-state n-channel transistors in

15 the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a sum of gate capacitances of the operating-state p-channel transistors and interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a sum of

20 gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first

and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a sum of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a sum of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a sum of gate capacitances of the operating-state p-channel transistors and interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a sum of gate capacitances of the operating-state n-channel transistors and interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the operating-state gate circuits and an ~~averaged~~ average value of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined

to be a gate width of a model n-channel transistor; a product of the number of the operating-state gate circuits and a sum of both a first averaged average value of gate capacitances of the operating-state p-channel transistors and a second averaged average value of interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load capacity capacitor; and a product of the number of the operating-state gate circuits and a sum of both a first averaged average value of gate capacitances of the operating-state n-channel transistors and a second averaged average value of interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load capacity capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load capacities capacitors is designed.

It is also preferable that a half of a product of the number of the operating-state gate circuits and an averaged average value of gate widths of the operating-state p-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a product of the number of the operating-state gate circuits and an averaged average value of gate widths of operating-state n-channel transistors in the operating-state of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the operating-state gate circuits and a sum of both a first averaged average value of gate capacitances of the operating-state

p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the number of the  
5 operating-state gate circuits and a sum of both a first ~~averaged~~ average value of gate capacitances of the operating-state n-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the operating-state n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic  
10 gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of all p-channel transistors of  
15 the constituting gate circuits and ~~[[an]]~~ information about operational rate of operating-state p-channel transistors in the operating-state are utilized to decide a gate width of a model p-channel transistor; ~~informations~~ information about gate widths of all n-channel transistors of the constituting gate circuits and ~~[[an]]~~ information about operational rate of  
20 operating-state n-channel transistors in the operating-state are utilized to decide a gate width of a model n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all p-channel transistors

and a first power terminal and ~~informations~~ information about the operational rate are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about the operational rate are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, an average operational rate of the gate circuits, and an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, an average operational rate of the gate circuits, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a product of the number of the all gate circuits, an average

operational rate of the gate circuits, and a sum of both a first ~~averaged~~  
average value of gate capacitances of the all n-channel transistors and a  
second ~~averaged~~ average value of interconnection capacitances between the  
all n-channel transistors and the second power terminal is defined to be a  
5 model second load ~~capacity~~ capacitor, whereby the logic gate circuit part  
comprising a single pair of p-channel and n-channel transistors and a single  
pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the  
all gate circuits, an average operational rate of the gate circuits, and an  
10 ~~averaged~~ average value of gate widths of the all p-channel transistors in the  
all of the constituting gate circuits is defined to be a gate width of a model  
p-channel transistor; a half of a product of the number of the all gate  
circuits, an average operational rate of the gate circuits, and an ~~averaged~~  
average value of gate widths of all n-channel transistors in the all of the  
15 constituting gate circuits is defined to be a gate width of a model n-channel  
transistor; a half of a product of the number of the all gate circuits, an  
average operational rate of the gate circuits, and a sum of both a first  
~~averaged~~ average value of gate capacitances of the all p-channel transistors  
and a second ~~averaged~~ average value of interconnection capacitances  
20 between the all p-channel transistors and the first power terminal is defined  
to be a model first load ~~capacity~~ capacitor; and a half of a product of the  
number of the all gate circuits, an average operational rate of the gate  
circuits, and a sum of both a first ~~averaged~~ average value of gate  
capacitances of the all n-channel transistors and a second ~~averaged~~ average



value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load capacity capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second  
5 load capacities capacitors is designed.

It is also preferable that a product of the number of the all gate circuits, a maximum operational rate of the gate circuits, and an averaged average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel  
10 transistor; a product of the number of the all gate circuits, the maximum operational rate of the gate circuits, and an averaged average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the maximum operational rate of the  
15 gate circuits, and a sum of both a first averaged average value of gate capacitances of the all p-channel transistors and a second averaged average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load capacity capacitor; and a product of the number of the all gate circuits, the  
20 maximum operational rate of the gate circuits, and a sum of both a first averaged average value of gate capacitances of the all n-channel transistors and a second averaged average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load capacity capacitor, whereby the logic

gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a half of a product of the number of the  
5 all gate circuits, a maximum operational rate of the gate circuits, and an  
~~averaged~~ average value of gate widths of the all p-channel transistors in the  
all of the constituting gate circuits is defined to be a gate width of a model  
p-channel transistor; a half of a product of the number of the all gate  
circuits, the maximum operational rate of the gate circuits, and an ~~averaged~~  
10 average value of gate widths of all n-channel transistors in the all of the  
constituting gate circuits is defined to be a gate width of a model n-channel  
transistor; a half of a product of the number of the all gate circuits, the  
maximum operational rate of the gate circuits, and a sum of both a first  
~~averaged~~ average value of gate capacitances of the all p-channel transistors  
15 and a second ~~averaged~~ average value of interconnection capacitances  
between the all p-channel transistors and the first power terminal is defined  
to be a model first load ~~capacity~~ capacitor; and a half of a product of the  
number of the all gate circuits, the maximum operational rate of the gate  
circuits, and a sum of both a first ~~averaged~~ average value of gate  
20 capacitances of the all n-channel transistors and a second ~~averaged~~ average  
value of interconnection capacitances between the all n-channel transistors  
and the second power terminal is defined to be a model second load  
~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs  
of p-channel and n-channel transistors and two pairs of first and second

load ~~capacities~~ capacitors is designed.

It is also preferable that in the first sequential processes, ~~informations~~ information about gate widths of all p-channel transistors of the constituting gate circuits and ~~informations~~ information about currents of  
5 basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model p-channel transistor; ~~informations~~ information about gate widths of all n-channel transistors of the constituting gate circuits and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide a gate width of a model  
10 n-channel transistor; ~~informations~~ information about gate ~~capacities~~ capacitances of the all p-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all p-channel transistors and a first power terminal and ~~informations~~ information about currents of basic gate circuits and the constituting gate  
15 circuits are utilized to decide a model first load ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances of the all n-channel transistors of the constituting gate circuits and ~~informations~~ information about interconnection capacitances between the all n-channel transistors and a second power terminal and ~~informations~~ information about  
20 currents of basic gate circuits and the constituting gate circuits are utilized to decide a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising at least a pair of p-channel and n-channel transistors and at least a pair of first and second load ~~capacities~~ capacitors is designed.

It is also preferable that a product of the number of the all gate

circuits, and a power current ratio of an averaged average current value of the basic gate circuits to an averaged average current value of the constituting gate circuits, and an averaged average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a product of the number of the all gate circuits, the power current ratio, and an averaged average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a product of the number of the all gate circuits, the power current ratio, and a sum of both a first averaged average value of gate capacitances of the all p-channel transistors and a second averaged average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load capacity capacitor; and a product of the number of the all gate circuits, the power current ratio, and a sum of both a first averaged average value of gate capacitances of the all n-channel transistors and a second averaged average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load capacity capacitor, whereby the logic gate circuit part comprising a single pair of p-channel and n-channel transistors and a single pair of first and second load capacities capacitors is designed.

It is also preferable that a half of a product of the number of the all gate circuits, and a power current ratio of an averaged average current value of the basic gate circuits to an averaged average current value of the

constituting gate circuits, and an ~~averaged~~ average value of gate widths of the all p-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model p-channel transistor; a half of a product of the number of the all gate circuits, the power current ratio, and

5 an ~~averaged~~ average value of gate widths of all n-channel transistors in the all of the constituting gate circuits is defined to be a gate width of a model n-channel transistor; a half of a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all p-channel transistors and a second

10 ~~averaged~~ average value of interconnection capacitances between the all p-channel transistors and the first power terminal is defined to be a model first load ~~capacity~~ capacitor; and a half of a product of the number of the all gate circuits, the power current ratio, and a sum of both a first ~~averaged~~ average value of gate capacitances of the all n-channel transistors and a

15 second ~~averaged~~ average value of interconnection capacitances between the all n-channel transistors and the second power terminal is defined to be a model second load ~~capacity~~ capacitor, whereby the logic gate circuit part comprising two pairs of p-channel and n-channel transistors and two pairs of first and second load ~~capacities~~ capacitors is designed.

20 It is also preferable that in the second sequential processes, ~~informations~~ information about ON-resistances of non-operating-state transistors in the non-operating-state of the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about gate ~~capacities~~ capacitances

of the non-operating-state transistors in the non-operating-state of the constituting gate circuits and about interconnection capacitances between the operating-state transistors and a power terminal are utilized to decide the equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal  
5 capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a reciprocal of a sum of reciprocals of ON-resistances of non-operating p-channel transistors in the non-operating state is defined to be an ON-resistance of a third equivalent  
10 internal ~~capacity~~ capacitor; a double of a reciprocal of a sum of reciprocals of ON-resistances of non-operating n-channel transistors in the non-operating state is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; an arithmetic mean of a sum of gate  
~~capacities~~ capacitances of the non-operating p-channel transistors and a  
15 sum of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and an arithmetic mean of a sum of gate  
~~capacities~~ capacitances of the non-operating n-channel transistors and  
a sum of interconnection ~~capacities~~ capacitances between the non-operating  
20 n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that a double of a product of an averaged

average value of ON-resistances of non-operating p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of

5 ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~

10 capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an

15 ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part

20 comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that in the second sequential processes, ~~informations~~ information about an ~~averaged~~ average value of ON-resistances of all transistors included in the constituting gate circuits and the number of non-operating gate circuits are utilized to decide an

ON-resistance of an equivalent internal ~~capacity~~ capacitor; and  
infor~~mations~~ information about an ~~averaged~~ average value of gate  
capacities capacitances of the non-operating-state transistors in the  
non-operating-state of the constituting gate circuits, and the number of  
5 non-operating gate circuits as well as infor~~mations~~ information about an  
~~averaged~~ average value of interconnection capacitances between the  
operating-state transistors and a power terminal are utilized to decide the  
equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal  
capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor  
10 is designed.

It is also preferable that the number of non-operating gate circuits  
in the non-operating state is defined to be a product of a total number of the  
constituting logic gate included in the ~~semiconductor~~ integrated circuit and  
a remainder by subtracting an average operational rate from 1; a double of  
15 a product of an ~~averaged~~ average value of ON-resistances of non-operating  
p-channel transistors in the non-operating state and a reciprocal of the  
number of non-operating gate circuits is defined to be an ON-resistance of  
a third equivalent internal ~~capacity~~ capacitor; a double of a product of an  
~~averaged~~ average value of ON-resistances of non-operating n-channel  
20 transistors in the non-operating state and a reciprocal of the number of the  
non-operating gate circuit is defined to be an ON-resistance of a second  
equivalent internal ~~capacity~~ capacitor; a product of the number of the  
non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average  
value of gate ~~capacities~~ capacitances of the non-operating p-channel



transistors and an averaged average value of interconnection capacities  
capacitances between the non-operating p-channel transistors and a first  
power terminal is defined to be the second equivalent internal capacity  
capacitor; and a product of the number of the non-operating gate circuit and  
5 an arithmetic mean of an averaged average value of gate capacities  
capacitances of the non-operating n-channel transistors and an averaged  
average value of interconnection capacities capacitances between the  
non-operating n-channel transistors and a second power terminal is defined  
to be the third equivalent internal capacity capacitor, whereby the  
10 equivalent internal capacitive part comprising at least the equivalent  
internal capacity capacitor is designed.

It is also preferable that the number of non-operating gate circuits  
in the non-operating state is defined to be a product of a total number of the  
constituting logic gate included in the ~~semiconductor~~ integrated circuit and  
15 a remainder by subtracting a maximum operational rate from 1; a double of  
a product of an averaged average value of ON-resistances of non-operating  
p-channel transistors in the non-operating state and a reciprocal of the  
number of non-operating gate circuits is defined to be an ON-resistance of  
a third equivalent internal capacity capacitor; a double of a product of an  
20 averaged average value of ON-resistances of non-operating n-channel  
transistors in the non-operating state and a reciprocal of the number of the  
non-operating gate circuit is defined to be an ON-resistance of a second  
equivalent internal capacity capacitor; a product of the number of the  
non-operating gate circuit and an arithmetic mean of an averaged average

value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that ~~informations~~ information about an ~~averaged~~ average value of ON-resistances of all transistors included in the constituting gate circuits and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits are utilized to decide an ON-resistance of an equivalent internal ~~capacity~~ capacitor; and ~~informations~~ information about an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating-state transistors in the non-operating-state of the constituting gate circuits, and ~~informations~~ information about currents of basic gate circuits and the constituting gate circuits as well as ~~informations~~ information about an ~~averaged~~ average value of interconnection capacitances between the operating-state transistors and a power terminal are utilized to decide the equivalent

internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent internal ~~capacity~~ capacitor is designed.

It is also preferable that the number of non-operating gate circuits in the non-operating state is defined to be a product of the total number of  
5 the constituting gate circuits included in the ~~semiconductor~~ integrated circuit and a power current ratio which is defined to be a ratio of an ~~averaged~~ average current value of all of basic gate circuits to an ~~averaged~~ average current value of all of the constituting gate circuits; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating  
10 p-channel transistors in the non-operating state and a reciprocal of the number of non-operating gate circuits is defined to be an ON-resistance of a third equivalent internal ~~capacity~~ capacitor; a double of a product of an ~~averaged~~ average value of ON-resistances of non-operating n-channel transistors in the non-operating state and a reciprocal of the number of the  
15 non-operating gate circuit is defined to be an ON-resistance of a second equivalent internal ~~capacity~~ capacitor; a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating p-channel transistors and an ~~averaged~~ average value of interconnection ~~capacities~~ capacitances between the non-operating p-channel transistors and a first  
20 power terminal is defined to be the second equivalent internal ~~capacity~~ capacitor; and a product of the number of the non-operating gate circuit and an arithmetic mean of an ~~averaged~~ average value of gate ~~capacities~~ capacitances of the non-operating n-channel transistors and an ~~averaged~~

average value of interconnection ~~capacities~~ capacitances between the non-operating n-channel transistors and a second power terminal is defined to be the third equivalent internal ~~capacity~~ capacitor, whereby the equivalent internal capacitive part comprising at least the equivalent  
5 internal ~~capacity~~ capacitor is designed.

It is also preferable that the equivalent internal capacitive part is placed between the logic gate circuit part and a power system side.

It is also preferable that the power model is ~~deigned~~ designed for simulation to a current distribution over a circuit board on which the  
10 ~~semiconductor~~ integrated circuit is mounted.

It is also preferable that the power model is ~~deigned~~ designed for an electro-magnetic interference simulation to an electromagnetic field distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

15 It is also preferable that the computer program further includes a first simulation program for analysis to circuits.

It is also preferable that the first simulation program is to obtain a current distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

20 It is also preferable that the computer program ~~further more~~ furthermore includes a second simulation program for analysis to electromagnetic field to obtain a distribution of electromagnetic field over the circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

The fifth present invention provides a simulator for simulating an electro-magnetic interference. The simulator comprises: a circuit analyzing simulator being accessible to a first storage medium for receiving a power model for a ~~semiconductor~~ an integrated circuit, and also being connected  
5 to a second storage medium for receiving ~~informations~~ information about a circuit board on which the ~~semiconductor~~ integrated circuit is mounted, so that the circuit analyzing simulator analyzes the power model to obtain a current distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted; an electromagnetic field analyzing simulator  
10 being accessible to the circuit analyzing simulator for receiving the current distribution, so that the electromagnetic field analyzing simulator analyzes an electromagnetic field distribution over the circuit board on which the ~~semiconductor~~ integrated circuit is mounted, wherein the power model comprises a logic gate circuit part representing an operating part of the  
15 ~~semiconductor~~ integrated circuit and an equivalent internal capacitive part representing a non-operating part of the ~~semiconductor~~ integrated circuit.

It is also preferable that the power model is independently provided for each of plural power systems which are independent from each other and included in the ~~semiconductor~~ integrated circuit.

20 It is also preferable that internal circuit configurations of the ~~semiconductor~~ integrated circuit are divided into plural blocks on the basis of arrangement ~~informations~~ information, and the power model is provided for each of the plural blocks.

It is also preferable that internal circuit configurations of the ~~semiconductor~~ integrated circuit are divided into plural groups, each of the plural groups comprises a same timing group which includes logic gate circuits having individual signal transmission delay times fallen in a group-belonging predetermined time range which belongs to each of the plural groups, and the power model is provided for each of the plural groups.

It is also preferable that the power model further comprises a signal source connected to the logic gate circuit part for supplying a frequency-fixed signal to the logic gate circuit part, so that the logic gate circuit part represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal, and the equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuit.

It is also preferable that the equivalent internal capacitive part further represents operating-irrelevant fixed parts of the ~~semiconductor~~ integrated circuit.

It is also preferable that the logic gate circuit part is connected between first and second ~~powers~~ power terminals, and the equivalent internal capacitive part is also connected between the first and second ~~powers~~ power terminals.

It is also preferable that the logic gate circuit part further comprises a single pair of an inverter circuit and a load capacitive element, and the inverter circuit is connected between the first and second ~~powers~~

power terminals and the load capacitive element is also connected between the first and second ~~powers~~ power terminals, and the load capacitive element is placed between the inverter circuit and the equivalent internal capacitive part.

5           It is also preferable that the load capacitive element comprises a series connection of a first load capacitance and a second load capacitance between the first and second ~~powers~~ power terminals, and an intermediate point between the first and second load capacitances is connected to an output terminal of the inverter circuit.

10           It is also preferable that the equivalent internal capacitive part further comprises at least an equivalent internal capacitive element connected between the first and second ~~powers~~ power terminals.

          It is also preferable that a plurality of the equivalent internal capacitive element is connected between the first and second ~~powers~~ power  
15 terminals, and the equivalent internal capacitive element comprises a series connection of a capacitance and a resistance between the first and second ~~powers~~ power terminals.

          It is also preferable that the inverter circuit comprises a series connection of a p-channel MOS field effect transistor and an n-channel  
20 MOS field effect transistor, and gate electrodes of the p-channel and n-channel MOS field effect transistors are connected to a clock signal source for applying a clock signal to the gate electrodes of the p-channel and n-channel MOS field effect transistors.

It is also preferable that the logic gate circuit part further comprises plural pairs of an inverter circuit and a load capacitive element, and the inverter circuit is connected between the first and second ~~powers~~ power terminals and the load capacitive element is also connected between  
5 the first and second ~~powers~~ power terminals, and in each pair, the load capacitive element is placed closer to the equivalent internal capacitive part than the inverter circuit.

It is also preferable that the load capacitive element comprises a series connection of a first load capacitance and a second load capacitance  
10 between the first and second ~~powers~~ power terminals, and an intermediate point between the first and second load capacitances is connected to an output terminal of the inverter circuit.

It is also preferable that the equivalent internal capacitive part further comprises at least an equivalent internal capacitive element  
15 connected between the first and second ~~powers~~ power terminals.

It is also preferable that a plurality of the equivalent internal capacitive element is connected between the first and second ~~powers~~ power terminals, and the equivalent internal capacitive element comprises a series connection of a capacitance and a resistance between the first and second  
20 ~~powers~~ power terminals.

It is also preferable that the inverter circuit comprises a series connection of a p-channel MOS field effect transistor and an n-channel MOS field effect transistor, and gate electrodes of the p-channel and n-channel MOS field effect transistors are connected to a clock signal



source for applying a clock signal to the gate electrodes of the p-channel and n-channel MOS field effect transistors.

It is also preferable that the equivalent internal capacitive part is placed between the logic gate circuit part and a power system side.

5           Accordingly, the present invention also provides a novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit free from the above problems.

          The present invention also provides a novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
10 circuit, wherein the power model allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

          The present invention also provides a novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
15 circuit, wherein the power model makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

          The present invention also provides a novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
20 circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit free from the above problems.

10 The present invention also provides a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the method allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

15 The present invention also provides a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the method makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

20 The present invention also provides a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate

electro-magnetic interference simulation from a power system of a printed board.

5 The present invention also provides a novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

10 The present invention also provides a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit free from the above problems.

15 The present invention also provides a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the electro-magnetic interference simulator allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

20 The present invention also provides a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the electro-magnetic interference simulator makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power

system of a printed board.

The present invention also provides a novel electro-magnetic interference simulator using a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein  
5 the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel electro-magnetic  
10 interference simulator using a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation  
15 from a power system of a printed board.

The present invention also provides a novel power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit free from the above problems.

20 The present invention also provides a novel power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model preparation computer program allows an extremely accurate electro-magnetic interference simulation from a power

system of a printed board.

The present invention also provides a novel power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model preparation computer program makes it  
5 easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel power model preparation computer program for preparing a power model for an  
10 electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel power model preparation computer program for preparing a power model for an  
15 electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the  
20 circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to a

~~semiconductor~~ an integrated circuit free from the above problems.

The present invention also provides a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to a  
5 ~~semiconductor~~ an integrated circuit, wherein the power model preparation computer program allows an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel storage medium for storing a power model preparation computer program for preparing a  
10 power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model preparation computer program makes it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

15 The present invention also provides a novel storage medium for storing a power model preparation computer program for preparing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and  
20 interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel storage medium for storing a power model preparation computer program for preparing a

power model for an electro-magnetic interference simulation to a  
~~semiconductor~~ an integrated circuit, wherein the power model is designed  
on the basis of all ~~informations~~ information about connections and  
interconnections of the circuits to make it easy to conduct an extremely  
5 accurate electro-magnetic interference simulation from a power system of a  
printed board.

The present invention also provides a novel power model design  
support system for supporting a design for a power model for an  
electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
10 circuit free from the above problems.

The present invention also provides a novel power model design  
support system for supporting a design for a power model for an  
electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
circuit, wherein the power model allows an extremely accurate  
15 electro-magnetic interference simulation from a power system of a printed  
board.

The present invention also provides a novel power model design  
support system for supporting a design for a power model for an  
electro-magnetic interference simulation to ~~a semiconductor~~ an integrated  
20 circuit, wherein the power model makes it easy to conduct an extremely  
accurate electro-magnetic interference simulation from a power system of a  
printed board.

The present invention also provides a novel power model design  
support system for supporting a design for a power model for an

electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to allow an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

The present invention also provides a novel power model design support system for supporting a design for a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit, wherein the power model is designed on the basis of all ~~informations~~ information about connections and interconnections of the circuits to make it easy to conduct an extremely accurate electro-magnetic interference simulation from a power system of a printed board.

## PREFERRED EMBODIMENTS

### 15 FIRST EMBODIMENT :

A first embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 3 is a circuit diagram illustrative of a first novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a first embodiment in accordance with the present invention. The first novel power model 18 has a first power terminal 7 and a second power terminal 8. The first novel power model 18 also has the following elements. An operational signal source (a clock signal source) 1 is provided which is connected to the second power terminal 8. An inverter circuit 2 is also



provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The inverter circuit 2 is further connected to the operational signal source (a clock signal source) 1 for receiving a ~~lock~~ clock signal from the operational signal source (a clock signal source) 1.

5 First and second load ~~capacities~~ capacitors 5 and 6 are also provided which are connected in series between the first and second ~~powers~~ power terminals 7 and 8, wherein the first load ~~capacity~~ capacitor 5 is directly connected to the first power terminal 7, whilst the second load ~~capacity~~ capacitor 6 is directly connected to the first power terminal 8. The inverter  
10 circuit 2 comprises a series connection of a p-channel MOS field effect transistor 3 and an n-channel MOS field effect transistor 4 between the first and second ~~powers~~ power terminals 7 and 8. A gate of the p-channel MOS field effect transistor 3 is connected to the operational signal source (a clock signal source) 1 for receiving a ~~lock~~ clock signal from the operational  
15 signal source (a clock signal source) 1. A gate of the n-channel MOS field effect transistor 4 is also connected to the operational signal source (a clock signal source) 1 for receiving a ~~lock~~ clock signal from the operational signal source (a clock signal source) 1. The p-channel MOS field effect transistor 3 is connected between the first power terminal 7 and an output  
20 terminal 71 of the inverter circuit 2. The n-channel MOS field effect transistor 4 is connected between the second power terminal 8 and the output terminal 71 of the inverter circuit 2. The output terminal 71 of the inverter circuit 2 is connected to an intermediate point between the first and second load ~~capacities~~ capacitors 5 and 6. A first equivalent internal

capacitive element 9 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The series connection of the first and second load ~~capacities~~ capacitors 5 and 6 is placed between the inverter circuit 2 and the first equivalent internal capacitive element 9. The first  
5 equivalent internal capacitive element 9 further comprises a series connection of a first equivalent internal ~~capacity~~ capacitor 12 and a first equivalent internal series resistance 13. The first equivalent internal ~~capacity~~ capacitor 12 is directly connected to the first power terminal 7, ~~whilst~~ while the first equivalent internal series resistance 13 is directly  
10 connected to the second power terminal 8. A second equivalent internal capacitive element 10 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The first equivalent internal capacitive element 9 is placed between the series connection of the first and second load ~~capacities~~ capacitors 5 and 6 and the second equivalent internal  
15 capacitive element 10. The second equivalent internal capacitive element 10 further comprises a series connection of a second equivalent internal ~~capacity~~ capacitor 15 and a second equivalent internal series resistance 14. The second equivalent internal ~~capacity~~ capacitor 15 is directly connected to the second power terminal 8, ~~whilst~~ while the second equivalent internal  
20 series resistance 14 is directly connected to the first power terminal 7. A third equivalent internal capacitive element 11 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The second equivalent internal capacitive element 10 is placed between the first equivalent internal capacitive element 9 and the third equivalent

internal capacitive element 11. The third equivalent internal capacitive element 11 further comprises a series connection of a third equivalent internal ~~capacity~~ capacitor 17 and a third equivalent internal series resistance 16. The third equivalent internal ~~capacity~~ capacitor 17 is directly  
5 connected to the second power terminal 8, ~~whilst~~ while the third equivalent internal series resistance 16 is directly connected to the first power terminal 7. An equivalent internal capacitive part comprising the first, second and third equivalent internal capacitive elements 9, 10 and 11 is placed between the inverter circuit 2 and the power side having the first and second ~~powers~~  
10 power terminals 7 and 8. The gate circuit comprises the inverter circuit 2 and the series connection of the first and second load ~~capacities~~ capacitors 5 and 6. Namely, the equivalent internal capacitive part is placed between the gate circuit and the power side having the first and second ~~powers~~ power terminals 7 and 8. The operational signal source (a clock signal  
15 source) 1 generates a frequency-fixed signal such as a clock signal.

The logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the  
20 ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state, even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the

operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The logic gate circuit having the inverter circuit 2 and the first and second load ~~capacitances~~ capacitors 5 and 6 corresponds to the operating state parts of the ~~semiconductor~~ integrated circuit. The first equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit.

The first novel electro-magnetic interference (EMI) simulation power mode is represented in the transistor description format for conducting the simulation to the radiation electro-magnetic field generated on the printed board. This transistor description format large scale integrated circuit power model is largely reduced in the number of transistors constituting this model. The electro-magnetic interference (EMI) simulator utilizes this transistor description format large scale integrated circuit power model to find a power current which flows on an interconnection of a printed board. This transistor description format large scale integrated circuit power model is prepared by extracting operating parts from a net-list for the large scale integrated circuit to reduce the number of transistors constituting this model. Non-operating state parts of the large scale integrated circuit are simplified to be incorporated into the

power model. Namely, the transistor description format large scale integrated circuit power model includes the operating state parts extracted from the net-list and the simplified non-operating state parts, so that all of the parts of the large scale integrated circuit are utilized to prepare the  
5 transistor description format large scale integrated circuit power model.

The power system of the large scale integrated circuit is modeled into the logic gate part and the equivalent internal capacitive part. As compared to the conventional transistor description format large scale integrated circuit power model, a calculation load to the electro-magnetic  
10 interference (EMI) simulator is reduced, thereby making it easy to conduct the power current analysis. The non-operating state parts of the large scale integrated circuit are considered on the electro-magnetic interference (EMI) simulation, whereby the large scale integrated circuit model shows similar ~~operations~~ operation or ~~behaviors~~ behavior to the actual ~~operations~~  
15 operation or ~~behaviors~~ behavior of the actual large scale integrated circuit. This makes it possible to find a highly accurate power current of the large scale integrated circuit. Since the confidential detailed ~~informations~~ information about the internal circuit configurations of the large scale integrated circuit and the device structures are not included in this transistor  
20 description format large scale integrated circuit power model, the maker who manufactures the large scale integrated circuit is likely to show this transistor description format large scale integrated circuit power model to the user with keeping the detailed ~~informations~~ information to be confidential.

SECOND EMBODIMENT :

A second embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 4 is a circuit diagram illustrative of a second novel power model for an electro-magnetic interference simulation to a semiconductor ~~an~~ an integrated circuit in a second embodiment in accordance with the present invention. The second novel power model 29 has a first power terminal 7 and a second power terminal 8. The second novel power model 29 also has the following elements. An operational signal source (a clock signal source) 1 is provided which is connected to the second power terminal 8. A logic gate circuit part comprises two stages. A first stage has a first stage inverter circuit 19 and a first series connection of first and second first-stage load ~~capacities~~ capacitors 22 and 23. The first stage inverter circuit 19 is connected between the first and second ~~powers~~ power terminals 7 and 8. The first stage inverter circuit 19 is further connected to the operational signal source (a clock signal source) 1 for receiving a ~~lock~~ clock signal from the operational signal source (a clock signal source) 1. The first and second first-stage load ~~capacities~~ capacitors 22 and 23 are connected in series between the first and second ~~powers~~ power terminals 7 and 8, wherein the first first-stage load ~~capacity~~ capacitor 22 is directly connected to the first power terminal 7, ~~whilst~~ while the second first-stage load ~~capacity~~ capacitor 23 is directly connected to the first power terminal 8. The first stage inverter circuit 19 comprises a series connection of a p-channel MOS field effect transistor 20 and an n-channel MOS field effect transistor 21

between the first and second ~~powers~~ power terminals 7 and 8. A gate of the p-channel MOS field effect transistor 20 is connected to the operational signal source (a clock signal source) 1 for receiving a ~~look~~ clock signal from the operational signal source (a clock signal source) 1. A gate of the

5 n-channel MOS field effect transistor 21 is also connected to the operational signal source (a clock signal source) 1 for receiving a ~~look~~ clock signal from the operational signal source (a clock signal source) 1. The p-channel MOS field effect transistor 20 is connected between the first

10 power terminal 7 and an output terminal 71 of the first stage inverter circuit 19. The n-channel MOS field effect transistor 21 is connected between the second power terminal 8 and the output terminal 71 of the first stage inverter circuit 19. The output terminal 71 of the first stage inverter circuit 19 is connected to an intermediate point between the first and second first-stage load ~~capacities~~ capacitors 22 and 23. A second-stage has a

15 second-stage inverter circuit 24 and a second series connection of first and second second-stage load ~~capacities~~ capacitors 27 and 28. The second-stage inverter circuit 24 is connected between the first and second ~~powers~~ power terminals 7 and 8. The second-stage inverter circuit 24 is further connected to the output terminal 71 of the first-stage inverter circuit 19 for receiving

20 an output signal from the first-stage inverter circuit 19. The first and second second-stage load ~~capacities~~ capacitors 27 and 28 are connected in series between the first and second ~~powers~~ power terminals 7 and 8, wherein the first second-stage load ~~capacity~~ capacitor 27 is directly connected to the first power terminal 7, ~~whilst~~ while the second second-stage load ~~capacity~~

capacitor 28 is directly connected to the first power terminal 8. The second-stage inverter circuit 24 comprises a series connection of a p-channel MOS field effect transistor 25 and an n-channel MOS field effect transistor 26 between the first and second ~~powers~~ power terminals 7 and 8.

- 5 A gate of the p-channel MOS field effect transistor 25 is connected to the output terminal 71 of the first-stage inverter circuit 19 for receiving an output signal from the first-stage inverter circuit 19. A gate of the n-channel MOS field effect transistor 26 is also connected to the output terminal 71 of the first-stage inverter circuit 19 for receiving an output
- 10 signal from the first-stage inverter circuit 19. The p-channel MOS field effect transistor 25 is connected between the first power terminal 7 and an output terminal 72 of the second-stage inverter circuit 24. The n-channel MOS field effect transistor 26 is connected between the second power terminal 8 and the output terminal 72 of the second-stage inverter circuit 24.
- 15 The output terminal 72 of the second-stage inverter circuit 24 is connected to an intermediate point between the first and second second-stage load ~~capacities~~ capacitors 27 and 28. A first equivalent internal capacitive element 9 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The first equivalent internal capacitive
- 20 element 9 further comprises a series connection of a first equivalent internal ~~capacity~~ capacitor 12 and a first equivalent internal series resistance 13. The first equivalent internal ~~capacity~~ capacitor 12 is directly connected to the first power terminal 7, ~~whilst~~ while the first equivalent internal series resistance 13 is directly connected to the second power



terminal 8. A second equivalent internal capacitive element 10 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The first equivalent internal capacitive element 9 is placed between the series connection of the first and second second-stage load ~~capacities~~ capacitors 27 and 28 and the second equivalent internal capacitive element 10. The second equivalent internal capacitive element 10 further comprises a series connection of a second equivalent internal ~~capacity~~ capacitor 15 and a second equivalent internal series resistance 14. The second equivalent internal ~~capacity~~ capacitor 15 is directly connected to the second power terminal 8, ~~whilst~~ while the second equivalent internal series resistance 14 is directly connected to the first power terminal 7. A third equivalent internal capacitive element 11 is provided which is connected between the first and second ~~powers~~ power terminals 7 and 8. The second equivalent internal capacitive element 10 is placed between the first equivalent internal capacitive element 9 and the third equivalent internal capacitive element 11. The third equivalent internal capacitive element 11 further comprises a series connection of a third equivalent internal ~~capacity~~ capacitor 17 and a third equivalent internal series resistance 16. The third equivalent internal ~~capacity~~ capacitor 17 is directly connected to the second power terminal 8, ~~whilst~~ while the third equivalent internal series resistance 16 is directly connected to the first power terminal 7. An equivalent internal capacitive part comprising the first, second and third equivalent internal capacitive elements 9, 10 and 11 is placed between the second-stage inverter circuit 24 and the power side having the first and

second ~~powers~~ power terminals 7 and 8. The gate circuit comprises the first-stage inverter circuit 19 and the first series connection of the first and second first-stage load ~~capacities~~ capacitors 22 and 23, and further the second-stage inverter circuit 24 and the second series connection of the first and second second-stage load ~~capacities~~ capacitors 27 and 28. Namely, the equivalent internal capacitive part is placed between the logic gate circuit and the power side having the first and second ~~powers~~ power terminals 7 and 8. The operational signal source (a clock signal source) 1 generates a frequency-fixed signal such as a clock signal.

10           The two stage logic gate circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state, even the  
15 non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant  
20 capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The logic gate circuit having the first-stage inverter circuit 19 and the first and second first-stage load ~~capacitances~~ capacitors 22 and 23 and also having the

second-stage inverter circuit 24 and the first and second second-stage load capacitances capacitors 27 and 28 corresponds to the operating state parts of the semiconductor integrated circuit. The first equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the semiconductor integrated circuit. The second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the semiconductor integrated circuit.

In order to make the second novel power model equivalent in time-mean current to the first novel power model, respective gate electrode widths of the p-channel and n-channel MOS field effect transistors 20, 21, 25 and 26 of the second novel power model are reduced to one half of respective gate electrode widths of the p-channel and n-channel MOS field effect transistors 3 and 4 of the first power model. Further, respective gate electrode capacitances of the p-channel and n-channel MOS field effect transistors 20, 21, 25 and 26 of the second novel power model are reduced to one half of respective gate electrode capacitances of the p-channel and n-channel MOS field effect transistors 3 and 4 of the first power model. Further more, respective interconnection capacitances of the second novel power model are reduced to one half of respective interconnection capacitances of the first power model. Moreover, respective ON-resistances of the p-channel and n-channel MOS field effect transistors 20, 21, 25 and 26 of the second novel power model are increased to two times of respective ON-resistances of the p-channel and n-channel MOS field effect transistors 3 and 4 of the first power model.

The second novel electro-magnetic interference (EMI) simulation power mode is represented in the transistor description format for conducting the simulation to the radiation electro-magnetic field generated on the printed board. This transistor description format large scale  
5 integrated circuit power model is largely reduced in the number of transistors constituting this model. The electro-magnetic interference (EMI) simulator utilizes this transistor description format large scale integrated circuit power model to find a power current which flows on an interconnection of a printed board. This transistor description format large  
10 scale integrated circuit power model is prepared by extracting operating parts from a net-list for the large scale integrated circuit to reduce the number of transistors constituting this model. Non-operating state parts of the large scale integrated circuit are simplified to be incorporated into the power model. Namely, the transistor description format large scale  
15 integrated circuit power model includes the operating state parts extracted from the net-list and the simplified non-operating state parts, so that all of the parts of the large scale integrated circuit are utilized to prepare the transistor description format large scale integrated circuit power model.

The power system of the large scale integrated circuit is modeled  
20 into the logic gate part and the equivalent internal capacitive part. As compared to the conventional transistor description format large scale integrated circuit power model, a calculation load to the electro-magnetic interference (EMI) simulator is reduced, thereby making it easy to conduct the power current analysis. The non-operating state parts of the large scale

integrated circuit are considered on the electro-magnetic interference (EMI) simulation, whereby the large scale integrated circuit model shows similar ~~operations~~ operation or ~~behaviors~~ behavior to the actual ~~operations~~ operation or ~~behaviors~~ behavior of the actual large scale integrated circuit.

5 This makes it possible to find a highly accurate power current of the large scale integrated circuit. Since the confidential detailed ~~informations~~ information about the internal circuit configurations of the large scale integrated circuit and the device structures are not included in this transistor description format large scale integrated circuit power model, the maker  
10 who manufactures the large scale integrated circuit is likely to show this transistor description format large scale integrated circuit power model to the user with keeping the detailed ~~informations~~ information to be confidential.

15 THIRD EMBODIMENT :

A third embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 5 is a circuit diagram illustrative of a third novel power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a third  
20 embodiment in accordance with the present invention. The third novel power model 30 has two sets of ~~[[a]]~~ power ~~system~~ terminals, for example, a first set of a first power terminal and a second power terminal 33 and 34 and a second set of a third power terminal and a fourth power terminal 35 and 36, wherein the first set of the first and second ~~powers~~ power terminals

33 and 34 is independent from the second set of the third and fourth ~~powers~~  
power terminals 35 and 36. In this case, a power model 31 is provided for  
the first set of the first and second ~~powers~~ power terminals 33 and 34 as  
well as a power model 32 is also provided for the second set of the third  
5 and fourth ~~powers~~ power terminals 35 and 36. Each of the power models  
31 and 32 may comprise either the above described first or second novel  
power model described in the above first and second embodiments. Namely,  
the novel power model in accordance with the present invention is provided  
for each of the plural power ~~systems~~ terminals which are independent from  
10 each other.

#### FOURTH EMBODIMENT :

A fourth embodiment according to the present invention will be  
described in detail with reference to the drawings. FIG. 6 is a circuit  
15 diagram illustrative of a fourth novel power model for an electro-magnetic  
interference simulation to a ~~semiconductor~~ an integrated circuit in a fourth  
embodiment in accordance with the present invention. The fourth novel  
power model 30 has first and second ~~powers~~ power terminals 7 and 8. In  
this embodiment, the internal circuit ~~configurations~~ configuration of the  
20 ~~semiconductor~~ integrated circuit ~~are~~ is divided into plural blocks on the  
basis of arrangement ~~informations~~ information, and the power model 37 is  
provided for each of the plural blocks. Namely, the plural power models 37  
are individually provided for the plural blocks of the ~~semiconductor~~  
integrated circuit. Each of the plural power models 37 is connected

between the first and second ~~powers~~ power terminals 7 and 8. Namely, the plural power models 37 are connected in parallel to each other between the first and second ~~powers~~ power terminals 7 and 8. Each of the power models 37 may comprise either the above described first or second novel power model described in the above first and second embodiments. Namely, the novel power model in accordance with the present invention is provided for each of the plural blocks which are divided from the internal circuit ~~configurations~~ configuration of the ~~semiconductor~~ integrated circuit on the basis of the arrangement or ~~replacement~~ placement information of the circuit elements.

#### FIFTH EMBODIMENT :

A fifth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 7 is a circuit diagram illustrative of a fifth novel power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit in a fifth embodiment in accordance with the present invention. The fifth novel power model 30 has first and second ~~powers~~ power terminals 7 and 8. In this embodiment, the internal circuit ~~configurations~~ configuration of the ~~semiconductor~~ integrated circuit are is divided into plural groups. Each of the plural groups comprises the same timing group which includes logic gate circuits having individual signal transmission delay times fallen in a group-belonging predetermined time range which belongs to each of the plural groups. Namely, the internal circuit ~~configurations~~ configuration of

the ~~semiconductor~~ integrated circuit ~~are~~ is divided into plural groups on the basis of the signal transmission delay time of the logic gate circuits. The power model is provided for each of the plural groups. Namely, the plural power models 37 are individually provided for the plural blocks of the ~~semiconductor~~ integrated circuit. Each of the plural power models 37 is connected between the first and second ~~powers~~ power terminals 7 and 8. Namely, the plural power models 37 are connected in parallel to each other between the first and second ~~powers~~ power terminals 7 and 8. Each of the power models 37 may comprise either the above described first or second novel power model described in the above first and second embodiments. Namely, the novel power model in accordance with the present invention is provided for each of the plural blocks which are divided from the internal circuit configurations of the ~~semiconductor~~ integrated circuit on the basis of the signal transmission delay time of the logic gate circuits.

15

#### SIXTH EMBODIMENT :

A sixth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 8 is flow chart illustrative of novel processes for modeling the internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a first novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a sixth embodiment in accordance with the present invention. All of the circuit configuration ~~informations~~



information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S1, all of the gate circuits in an operating state in accordance with an operational frequency or a clock frequency are  
5 extracted from the data base. In second, third and fourth steps S2, S3 and S4, the all of the gate circuits in the operating state are modeled into a single gate circuit in order to prepare the above first power model described in the first embodiment in accordance with the present invention.

Namely, in the second step S2, the number “m” of the p-channel  
10 MOS field effect transistors in the operating state is confirmed. The sum “WP” of gate widths “WPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The sum “CP” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The sum “CL1” of  
15 interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the operating state is calculated.

In the third step S3, the number “m” of the n-channel MOS field effect transistors in the operating state is confirmed. The sum “WN” of gate  
20 widths “WNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The sum “CN” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The sum “CL2” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all

of the n-channel MOS field effect transistors in the operating state is calculated.

In the fourth step S4, the above logic gate circuit part of the above first novel power model shown in FIG. 3 is prepared. As described above, the logic gate circuit part of the above first novel power model comprises the single inverter circuit 2 and a single pair of the first and second load ~~capacities~~ capacitors 5 and 6. The inverter circuit 2 further comprises a single pair of the p-channel MOS field effect transistor 3 and the n-channel MOS field effect transistor 4. The sum "WP" is defined to be the gate width of the p-channel MOS field effect transistor 3. The sum "WN" is defined to be the gate width of the n-channel MOS field effect transistor 4. The sum ("CP" + "CL1") is defined to be the first load ~~capacity~~ capacitor 5. The sum ("CN" + "CL2") is defined to be the second load ~~capacity~~ capacitor 6. As a result, the logic gate circuit part of the first power model of the first embodiment is prepared.

#### SEVENTH EMBODIMENT :

A seventh embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 9 is flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in the first novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a seventh embodiment in

accordance with the present invention. All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

5 In a step S26, all of the gate circuits in an operating state in accordance with an operational frequency or a clock frequency are extracted from the data base. In second, third and fourth steps S27, S28 and S29, the all of the gate circuits in the operating state are modeled into two-stage gate circuits in order to prepare the above second power model described in the second embodiment in accordance with the present  
10 invention.

Namely, in the second step S27, the number “m” of the p-channel MOS field effect transistors in the operating state is confirmed. The sum “WP” of gate widths “WPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The sum “CP” of gate  
15 ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The sum “CL1” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the operating state is calculated.

20 In the third step S28, the number “m” of the n-channel MOS field effect transistors in the operating state is confirmed. The sum “WN” of gate widths “WNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The sum “CN” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the operating

state is calculated. The sum “CL2” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors in the operating state is calculated.

5           In the fourth step S29, the above logic gate circuit part of the above second novel power model shown in FIG. 4 is prepared. As described above, the logic gate circuit part of the above second novel power model comprises the first and second inverter circuits 19 and 24 and a first pair of the first and second load ~~capacities~~ capacitors 22 and 23 and a  
10   second pair of the third and fourth load ~~capacities~~ capacitors 27 and 28. The first inverter circuit 19 further comprises a single pair of the p-channel MOS field effect transistor 20 and the n-channel MOS field effect transistor 21. The second inverter circuit 24 further comprises another single pair of the p-channel MOS field effect transistor 25 and the n-channel MOS field  
15   effect transistor 26. The “WP/2” is defined to be the gate width of each of the p-channel MOS field effect transistors 20 and 25. The “WN/2” is defined to be the gate width of each of the n-channel MOS field effect transistors 21 and 26. The  $(“CP” + “CL1”)/2$  is defined to be each of the first and third load ~~capacities~~ capacitors 22 and 27. The  $(“CN” + “CL2”)/2$   
20   is defined to be each of the second and fourth load ~~capacities~~ capacitors 23 and 28. As a result, the logic gate circuit part of the second power model of the second embodiment is prepared.

EIGHTH EMBODIMENT :

An eighth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 10 is a flow chart illustrative of novel processes for modeling internal circuit configurations of a semiconductor an integrated circuit into a single gate circuit, wherein the novel processes are involved in a second novel method of designing a power model for an electro-magnetic interference simulation to a semiconductor an integrated circuit in an eighth embodiment in accordance with the present invention. All of the circuit configuration information information of the semiconductor integrated circuit are stored in a data base or a net list.

In a step S5, a total number “NgateOP” of the gate circuits in an operating state in accordance with an operational frequency or a clock frequency is counted from all of the circuit configuration information information stored in the data base. In second, third and fourth steps S6, S7 and S8, on the basis of the averaged average values of the gate widths and gate capacities capacitances of the n-channel and p-channel transistors and the averaged average values of the interconnection capacities capacitances between the drains and the powers power terminals of the n-channel and p-channel transistors, all of the gate circuits in the operating state are modeled into a single gate circuit in order to prepare the above first power model described in the first embodiment in accordance with the present invention.

Namely, in the second step S6, the averaged average value

“WPave” of gate widths “WPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The averaged average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the operating state is calculated. The averaged average value “CL1ave” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the operating state is calculated.

In the third step S7, the averaged average value “WNave” of gate widths “WNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The averaged average value “CNave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The averaged average value “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors in the operating state is calculated.

In the fourth step S8, the above logic gate circuit part of the above first novel power model shown in FIG. 3 is prepared. As described above, the logic gate circuit part of the above first novel power model comprises the single inverter circuit 2 and a single pair of the first and second load ~~capacities~~ capacitors 5 and 6. The inverter circuit 2 further comprises a single pair of the p-channel MOS field effect transistor 3 and the n-channel MOS field effect transistor 4. The product “NgateOP x WPave” of the total number “NgateOP” of the gate circuits in the operating state and the averaged average value “WPave” is calculated, so that the

product “NgateOP x WPave” is defined to be the gate width of the p-channel MOS field effect transistor 3. The product “NgateOP x WNavave” of the total number “NgateOP” of the gate circuits in the operating state and the averaged average value “WNavave” is calculated, so that the product  
5 “NgateOP x WNavave” is defined to be the gate width of the n-channel MOS field effect transistor 4. The product “NgateOP x (“CPave” + “CL1ave”)” of total number “NgateOP” of the gate circuits in the operating state and the averaged average value (“CPave” + “CL1ave”) is calculated, so that the product “NgateOP x (“CPave” + “CL1ave”)” is defined to be the first load  
10 capacity capacitor 5. The product “NgateOP x (“CNave” + “CL2ave”)” of total number “NgateOP” of the gate circuits in the operating state and the averaged average value (“CNave” + “CL2ave”) is calculated, so that the product “NgateOP x (“CNave” + “CL2ave”)” is defined to be the second load capacity capacitor 6. As a result, the logic gate circuit part of the first  
15 power model of the first embodiment is prepared.

#### NINTH EMBODIMENT :

A ninth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 11 is flow chart  
20 illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a second novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a ninth embodiment in accordance

with the present invention. All of the circuit configuration ~~information~~  
information of the ~~semiconductor~~ integrated circuit are stored in a data base  
or a net list.

In a step S30, a total number “NgateOP” of the gate circuits in an  
5 operating state in accordance with an operational frequency or a clock  
frequency is counted from all of the circuit configuration ~~information~~  
information stored in the data base. In second, third and fourth steps S31,  
S32 and S33, on the basis of the ~~averaged~~ average values of the gate widths  
and gate ~~capacities~~ capacitances of the n-channel and p-channel transistors  
10 and the ~~averaged~~ average values of the interconnection ~~capacities~~  
capacitances between the drains and the ~~powers~~ power terminals of the  
n-channel and p-channel transistors, all of the gate circuits in the operating  
state are modeled into two-stage gate circuits in order to prepare the above  
second power model described in the second embodiment in accordance  
15 with the present invention.

Namely, in the second step S31, the ~~averaged~~ average value  
“WPave” of gate widths “WPn” of all of the p-channel MOS field effect  
transistors in the operating state is calculated. The ~~averaged~~ average value  
“CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS  
20 field effect transistors in the operating state is calculated. The ~~averaged~~  
average value “CLlave” of interconnection ~~capacities~~ capacitances “CLln”  
between drains and the first power terminal of all of the p-channel MOS  
field effect transistors in the operating state is calculated.

In the third step S32, the ~~averaged~~ average value “WNave” of



gate widths “WNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The averaged average value “CNave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the operating state is calculated. The averaged average value  
5 “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors in the operating state is calculated.

In the fourth step S33, the above logic gate circuit part of the above second novel power model shown in FIG. 4 is prepared. As  
10 described above, the logic gate circuit part of the above second novel power model comprises the first and second inverter circuits 19 and 24 and a first pair of the first and second load ~~capacities~~ capacitors 22 and 23 and a second pair of the third and fourth load ~~capacities~~ capacitors 27 and 28. The first inverter circuit 19 further comprises a single pair of the p-channel  
15 MOS field effect transistor 20 and the n-channel MOS field effect transistor 21. The second inverter circuit 24 further comprises another single pair of the p-channel MOS field effect transistor 25 and the n-channel MOS field effect transistor 26. The product “NgateOP x WPave” of the total number “NgateOP” of the gate circuits in the operating state and the averaged  
20 average value “WPave” is calculated, so that a half “(NgateOP x WPave)/2” of the product “NgateOP x WPave” is defined to be the gate width of each of the p-channel MOS field effect transistors 20 and 25. The product “NgateOP x WNave” of the total number “NgateOP” of the gate circuits in the operating state and the averaged average value “WNave” is

calculated, so that a half  $(N_{gateOP} \times W_{Nave})/2$  of the product  $N_{gateOP} \times W_{Nave}$  is defined to be the gate width of each of the n-channel MOS field effect transistors 21 and 26. The product  $N_{gateOP} \times (C_{Pave} + C_{L1ave})$  of total number  $N_{gateOP}$  of the gate circuits in the operating state and the ~~averaged~~ average value  $(C_{Pave} + C_{L1ave})$  is calculated, so that a half  $\{N_{gateOP} \times (C_{Pave} + C_{L1ave})\}/2$  of the product  $N_{gateOP} \times (C_{Pave} + C_{L1ave})$  is defined to be each of the first and third load ~~capacities~~ capacitors 22 and 27. The product  $N_{gateOP} \times (C_{Nave} + C_{L2ave})$  of total number  $N_{gateOP}$  of the gate circuits in the operating state and the ~~averaged~~ average value  $(C_{Nave} + C_{L2ave})$  is calculated, so that a half  $\{N_{gateOP} \times (C_{Nave} + C_{L2ave})\}/2$  of the product  $N_{gateOP} \times (C_{Nave} + C_{L2ave})$  is defined to be each of the second and fourth load ~~capacities~~ capacitors 23 and 28. As a result, the logic gate circuit part of the second power model of the second embodiment is prepared.

#### TENTH EMBODIMENT :

A tenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 12 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a third novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit in a tenth embodiment in accordance

with the present invention. All of the circuit configuration ~~informations~~  
information of the ~~semiconductor~~ integrated circuit are stored in a data base  
or a net list.

In a step S9, a total number “Ngate” of the all gate circuits  
5 included in the ~~semiconductor~~ integrated circuit is counted from all of the  
circuit configuration ~~informations~~ information stored in the data base. In  
second, third, fourth and fifth steps S10, S11, S12 and S13, on the basis of  
the ~~averaged~~ average values of the gate widths and gate ~~capacities~~  
capacitances of the n-channel and p-channel transistors and the ~~averaged~~  
10 average values of the interconnection ~~capacities~~ capacitances between the  
drains and the ~~powers~~ power terminals of the n-channel and p-channel  
transistors as well as an average operational rate, all of the gate circuits in  
the operating state are modeled into a single gate circuit in order to prepare  
the above first power model described in the first embodiment in  
15 accordance with the present invention.

Namely, in the second step S10, an average operational rate  
“ROPave” of the gate circuits is calculated, wherein the average  
operational rate is defined to be the ~~averaged~~ average value of the rate of  
the operating gate circuits in the operating state in accordance with an  
20 operational frequency or a clock frequency to the total gate circuits  
included in the ~~semiconductor~~ integrated circuit.

In the third step S11, the ~~averaged~~ average value “WPave” of  
gate widths “WPn” of all of the p-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~

average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL1ave” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the  
5 first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fourth step S12, the ~~averaged~~ average value “WNav” of gate widths “WNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~  
10 average value “CNav” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors  
15 included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S13, the above logic gate circuit part of the above first novel power model shown in FIG. 3 is prepared. As described above, the logic gate circuit part of the above first novel power model comprises the single inverter circuit 2 and a single pair of the first and second load  
20 ~~capacities~~ capacitors 5 and 6. The inverter circuit 2 further comprises a single pair of the p-channel MOS field effect transistor 3 and the n-channel MOS field effect transistor 4. The product “Ngate x ROPave x WPave” of the total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the ~~averaged~~ average value “WPave” is

calculated, so that the product “Ngate x ROPave x WPave” is defined to be the gate width of the p-channel MOS field effect transistor 3. The product “Ngate x ROPave x WNavave” of the total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value “WNavave” is calculated, so that the product “Ngate x ROPave x WNavave” is defined to be the gate width of the n-channel MOS field effect transistor 4. The product “Ngate x ROPave x (“CPave” + “CL1ave”)” of total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value (“CPave” + “CL1ave”) is calculated, so that the product “Ngate x ROPave x (“CPave” + “CL1ave”)” is defined to be the first load capacity capacitor 5. The product “Ngate x ROPave x (“CNavave” + “CL2ave”)” of total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value (“CNavave” + “CL2ave”) is calculated, so that the product “Ngate x ROPave x (“CNavave” + “CL2ave”)” is defined to be the second load capacity capacitor 6. As a result, the logic gate circuit part of the first power model of the first embodiment is prepared.

#### ELEVENTH EMBODIMENT :

20           An eleventh embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 13 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a third novel method

of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit in an eleventh embodiment in accordance with the present invention. All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored  
5 in a data base or a net list.

In a step S34, a total number “Ngate” of the all gate circuits included in the ~~semiconductor~~ integrated circuit is counted from all of the circuit configuration ~~informations~~ information stored in the data base. In second, third, fourth and fifth steps S35, S36, S37 and S38, on the basis of  
10 the ~~averaged~~ average values of the gate widths and gate ~~capacities~~ capacitances of the n-channel and p-channel transistors and the ~~averaged~~ average values of the interconnection ~~capacities~~ capacitances between the drains and the ~~powers~~ power terminals of the n-channel and p-channel transistors as well as an average operational rate, all of the gate circuits in  
15 the operating state are modeled into two stage gate circuits in order to prepare the above second power model described in the second embodiment in accordance with the present invention.

Namely, in the second step S35, an average operational rate “ROPave” of the gate circuits is calculated, wherein the average  
20 operational rate is defined to be the ~~averaged~~ average value of the rate of the operating gate circuits in the operating state in accordance with an operational frequency or a clock frequency to the total gate circuits included in the ~~semiconductor~~ integrated circuit.

In the third step S36, the ~~averaged~~ average value “WPave” of

gate widths “WPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL1ave” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fourth step S37, the ~~averaged~~ average value “WNav” of gate widths “WNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CNav” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S38, the above logic gate circuit part of the above second novel power model shown in FIG. 4 is prepared. As described above, the logic gate circuit part of the above second novel power model comprises the first and second inverter circuits 19 and 24 and a first pair of the first and second load ~~capacities~~ capacitors 22 and 23 and a second pair of the third and fourth load ~~capacities~~ capacitors 27 and 28. The first inverter circuit 19 further comprises a single pair of the p-channel MOS

field effect transistor 20 and the n-channel MOS field effect transistor 21. The second inverter circuit 24 further comprises another single pair of the p-channel MOS field effect transistor 25 and the n-channel MOS field effect transistor 26. The product “Ngate x ROPave x WPave” of the total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value “WPave” is calculated, so that a half “{Ngate x ROPave x WPave}/2” of the product “Ngate x ROPave x WPave” is defined to be the gate width of each of the p-channel MOS field effect transistors 20 and 25. The product “Ngate x ROPave x WNavave” of the total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value “WNavave” is calculated, so that a half “{Ngate x ROPave x WNavave}/2” of the product “Ngate x ROPave x WNavave” is defined to be the gate width of each of the n-channel MOS field effect transistors 21 and 26. The product “Ngate x ROPave x (“CPave” + “CL1ave”)” of total number “Ngate” of the all gate circuits, and the average operational rate “ROPave”, and the averaged average value (“CPave” + “CL1ave”) is calculated, so that a half “{Ngate x ROPave x (“CPave” + “CL1ave”)} / 2” of the product “Ngate x ROPave x (“CPave” + “CL1ave”)” is defined to be each of the first and third load capacities capacitors 22 and 27. The product “Ngate x ROPave x (“CNavave” + “CL2ave”)” of total number “Ngate” of the all gate circuits in the operating state, and the average operational rate “ROPave”, and the averaged average value (“CNavave” + “CL2ave”) is calculated, so that a half “{Ngate x ROPave x (“CNavave” + “CL2ave”)} / 2” of the product “Ngate x



ROPave x (“CNave” + “CL2ave”)” is defined to be each of the second and fourth load ~~capacities~~ capacitors 23 and 28. As a result, the logic gate circuit part of the second power model of the second embodiment is prepared.

5

TWELFTH EMBODIMENT :

A twelfth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 14 is a flow chart illustrative of novel processes for modeling internal circuit configurations of a ~~semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a fourth novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit in a twelfth embodiment in accordance with the present invention. All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S14, a total number “Ngate” of the all gate circuits included in the ~~semiconductor~~ integrated circuit is counted from all of the circuit configuration ~~informations~~ information stored in the data base. In second, third, fourth and fifth steps S15, S16, S17 and S18, on the basis of the ~~averaged~~ average values of the gate widths and gate ~~capacities~~ capacitances of the n-channel and p-channel transistors and the ~~averaged~~ average values of the interconnection ~~capacities~~ capacitances between the drains and the ~~powers~~ power terminals of the n-channel and p-channel

transistors as well as a maximum operational rate, all of the gate circuits in the operating state are modeled into a single gate circuit in order to prepare the above first power model described in the first embodiment in accordance with the present invention.

5           Namely, in the second step S15, a maximum operational rate “ROPmax” of the gate circuits is calculated, wherein the maximum operational rate is defined to be the maximum value of the rate of the operating gate circuits in the operating state in accordance with an operational frequency or a clock frequency to the total gate circuits  
10 included in the ~~semiconductor~~ integrated circuit.

          In the third step S16, the ~~averaged~~ average value “WPave” of gate widths “WPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the  
15 p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL1ave” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

20           In the fourth step S17, the ~~averaged~~ average value “WNavave” of gate widths “WNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CNavave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~

integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

5                    In the fifth step S18, the above logic gate circuit part of the above first novel power model shown in FIG. 3 is prepared. As described above, the logic gate circuit part of the above first novel power model comprises the single inverter circuit 2 and a single pair of the first and second load ~~capacities~~ capacitors 5 and 6. The inverter circuit 2 further comprises a  
10   single pair of the p-channel MOS field effect transistor 3 and the n-channel MOS field effect transistor 4. The product “Ngate x ROPmax x WPave” of the total number “Ngate” of the all gate circuits, and the maximum operational rate “ROPmax”, and the ~~averaged~~ average value “WPave” is calculated, so that the product “Ngate x ROPmax x WPave” is defined to  
15   be the gate width of the p-channel MOS field effect transistor 3. The product “Ngate x ROPmax x WNavave” of the total number “Ngate” of the all gate circuits in the operating state, and the maximum operational rate “ROPmax”, and the ~~averaged~~ average value “WNavave” is calculated, so that the product “Ngate x ROPmax x WNavave” is defined to be the gate width of  
20   the n-channel MOS field effect transistor 4. The product “Ngate x ROPmax x (“CPave” + “CL1ave”)” of total number “Ngate” of the all gate circuits, and the maximum operational rate “ROPmax”, and the ~~averaged~~ average value (“CPave” + “CL1ave”) is calculated, so that the product “Ngate x ROPmax x (“CPave” + “CL1ave”)” is defined to be the first load

capacity capacitor 5. The product “Ngate x ROPmax x (“CNave” + “CL2ave”)” of total number “Ngate” of the all gate circuits, and the maximum operational rate “ROPmax”, and the averaged average value (“CNave” + “CL2ave”) is calculated, so that the product “Ngate x ROPmax x (“CNave” + “CL2ave”)” is defined to be the second load capacity capacitor 6. As a result, the logic gate circuit part of the first power model of the first embodiment is prepared.

#### THIRTEENTH EMBODIMENT :

10           A thirteenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 15 is a flow chart illustrative of novel processes for modeling internal circuit configurations of a semiconductor an integrated circuit into two-stage gate circuits, wherein the novel processes are involved in a fourth novel method  
15 of designing a power model for an electro-magnetic interference simulation to a semiconductor an integrated circuit in a thirteenth embodiment in accordance with the present invention. All of the circuit configuration informations information of the semiconductor integrated circuit are stored in a data base or a net list.

20           In a step S39, a total number “Ngate” of the all gate circuits included in the semiconductor integrated circuit is counted from all of the circuit configuration informations information stored in the data base. In second, third, fourth and fifth steps S40, S41, S42 and S43, on the basis of the averaged average values of the gate widths and gate capacities

capacitances of the n-channel and p-channel transistors and the averaged  
average values of the interconnection ~~capacities~~ capacitances between the  
drains and the ~~powers~~ power terminals of the n-channel and p-channel  
transistors as well as a maximum operational rate, all of the gate circuits in  
5 the operating state are modeled into two stage gate circuits in order to  
prepare the above second power model described in the second  
embodiment in accordance with the present invention.

Namely, in the second step S40, a maximum operational rate  
“ROPmax” of the gate circuits is calculated, wherein the maximum  
10 operational rate is defined to be the maximum value of the rate of the  
operating gate circuits in the operating state in accordance with an  
operational frequency or a clock frequency to the total gate circuits  
included in the ~~semiconductor~~ integrated circuit.

In the third step S41, the averaged average value “WPave” of  
15 gate widths “WPn” of all of the p-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated. The averaged  
average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the  
p-channel MOS field effect transistors included in the ~~semiconductor~~  
integrated circuit is calculated. The averaged average value “CLlave” of  
20 interconnection ~~capacities~~ capacitances “CLln” between drains and the  
first power terminal of all of the p-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated.

In the fourth step S42, the averaged average value “WNavave” of  
gate widths “WNn” of all of the n-channel MOS field effect transistors

included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~  
average value “CNave” of gate ~~capacities~~ capacitances “CNn” of all of the  
n-channel MOS field effect transistors included in the ~~semiconductor~~  
integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of  
5 interconnection ~~capacities~~ capacitances “CL2n” between drains and the  
second power terminal of all of the n-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S43, the above logic gate circuit part of the above  
second novel power model shown in FIG. 4 is prepared. As described  
10 above, the logic gate circuit part of the above second novel power model  
comprises the first and second inverter circuits 19 and 24 and a first pair of  
the first and second load ~~capacities~~ capacitors 22 and 23 and a second pair  
of the third and fourth load ~~capacities~~ capacitors 27 and 28. The first  
inverter circuit 19 further comprises a single pair of the p-channel MOS  
15 field effect transistor 20 and the n-channel MOS field effect transistor 21.  
The second inverter circuit 24 further comprises another single pair of the  
p-channel MOS field effect transistor 25 and the n-channel MOS field  
effect transistor 26. The product “Ngate x ROPmax x WPave” of the total  
number “Ngate” of the all gate circuits, and the maximum operational rate  
20 “ROPmax”, and the ~~averaged~~ average value “WPave” is calculated, so that  
a half “{Ngate x ROPmax x WPave}/2” of the product “Ngate x ROPmax  
x WPave” is defined to be the gate width of each of the p-channel MOS  
field effect transistors 20 and 25. The product “Ngate x ROPmax x  
WNave” of the total number “Ngate” of the all gate circuits, and the

maximum operational rate "ROPmax", and the ~~averaged~~ average value "WNav" is calculated, so that a half " $\{\text{Ngate} \times \text{ROPmax} \times \text{WNav}\}/2$ " of the product "Ngate x ROPmax x WNav" is defined to be the gate width of each of the n-channel MOS field effect transistors 21 and 26. The product  
5 "Ngate x ROPmax x ("CPave" + "CL1ave")" of total number "Ngate" of the all gate circuits, and the maximum operational rate "ROPmax", and the ~~averaged~~ average value ("CPave" + "CL1ave") is calculated, so that a half " $\{\text{Ngate} \times \text{ROPmax} \times (\text{"CPave"} + \text{"CL1ave"})\}/2$ " of the product "Ngate x ROPmax x ("CPave" + "CL1ave")" is defined to be each of the first and  
10 third load ~~capacities~~ capacitors 22 and 27. The product "Ngate x ROPmax x ("CNav" + "CL2ave")" of total number "Ngate" of the all gate circuits, and the maximum operational rate "ROPmax", and the ~~averaged~~ average value ("CNav" + "CL2ave") is calculated, so that a half " $\{\text{Ngate} \times \text{ROPmax} \times (\text{"CNav"} + \text{"CL2ave"})\}/2$ " of the product "Ngate x ROPmax x  
15 ("CNav" + "CL2ave")" is defined to be each of the second and fourth load ~~capacities~~ capacitors 23 and 28. As a result, the logic gate circuit part of the second power model of the second embodiment is prepared.

#### FOURTEENTH EMBODIMENT :

20 A fourteenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 16 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into a single gate circuit, wherein the novel processes are involved in a fifth novel method of

designing a power model for an electro-magnetic interference simulation to  
a ~~semiconductor~~ an integrated circuit in a fourteenth embodiment in  
accordance with the present invention. All of the circuit configuration  
~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored  
5 in a data base or a net list.

In a step S19, a total number “N<sub>gate</sub>” of the gate circuits in an  
operating state in accordance with an operational frequency or a clock  
frequency is counted from all of the circuit configuration ~~informations~~  
information stored in the data base. In second, third, fourth, fifth, sixth and  
10 seventh steps S20, S21, S22, S23, S24 and S25, on the basis of the  
~~averaged~~ average values of the gate widths and gate ~~capacities~~ capacitances  
of the n-channel and p-channel transistors and the ~~averaged~~ average values  
of the interconnection ~~capacities~~ capacitances between the drains and the  
~~powers~~ power terminals of the n-channel and p-channel transistors as well  
15 as an ~~averaged~~ average current value of the entire circuit configuration of  
the ~~semiconductor~~ integrated circuit and further an ~~averaged~~ average  
current value of a basic gate circuit prepared from the transistors and  
~~capacities~~ capacitors having the above ~~averaged~~ average values, all of the  
gate circuits in the operating state are modeled into a single gate circuit in  
20 order to prepare the above first power model described in the first  
embodiment in accordance with the present invention.

Namely, in the second step S20, an average current value “I<sub>ave</sub>”  
of entire circuit configurations of the ~~semiconductor~~ integrated circuits is  
calculated from all of the circuit configuration ~~informations~~ information of



the ~~semiconductor~~ integrated circuit stored in the data base.

In the third step S21, the ~~averaged~~ average value “WPave” of gate widths “WPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL1ave” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fourth step S22, the ~~averaged~~ average value “WNavave” of gate widths “WNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CNavave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S23, basic gate circuits are prepared in respective correspondence with the actual gate circuits included in the ~~semiconductor~~ integrated circuits, wherein ~~informations~~ information about the actual gate circuits are stored in the data base. The corresponding basic gate circuit is identical with the actual gate circuit in the circuit configurations, for

example, the circuit elements and the number of the circuit elements and placements and interconnection relationships between the circuit elements. However, the corresponding basic gate circuit is different from the actual gate circuit in the followings. All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate width “WPave”. All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate ~~capacity~~ capacitance “CPave”. All of the constitutional n-channel MOS field effect transistors of the basic gate circuit has the above ~~averaged~~ average gate width “WNave”. All of the constitutional n-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate ~~capacity~~ capacitance “CNave”. An average current value “IPRIave” of the above basic gate circuits in correspondence with the actual gate circuits included in the semiconductor device is calculated.

15           In the sixth step S24, a power current ratio “CI” is calculated, wherein the power current ratio “CI” is defined to be “IPRIave/Iave”, or the ratio of the average current value “IPRIave” of the above basic gate circuits to the average current value “Iave” of the above actual gate circuits.

20           In the seventh step S25, the above logic gate circuit part of the above first novel power model shown in FIG. 3 is prepared. As described above, the logic gate circuit part of the above first novel power model comprises the single inverter circuit 2 and a single pair of the first and second load ~~capacities~~ capacitors 5 and 6. The inverter circuit 2 further comprises a single pair of the p-channel MOS field effect transistor 3 and

the n-channel MOS field effect transistor 4. The product “Ngate x CI x WPave” of the total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the averaged average value “WPave” is calculated, so that the product “Ngate x ROPmax x WPave” is defined to be the gate width of the p-channel MOS field effect transistor 3. The product “Ngate x CI x WNavave” of the total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the averaged average value “WNavave” is calculated, so that the product “Ngate x CI x WNavave” is defined to be the gate width of the n-channel MOS field effect transistor 4. The product “Ngate x CI x (“CPave” + “CL1ave”)” of total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the averaged average value (“CPave” + “CL1ave”) is calculated, so that the product “Ngate x CI x (“CPave” + “CL1ave”)” is defined to be the first load capacity capacitor 5. The product “Ngate x CI x (“CNavave” + “CL2ave”)” of total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the averaged average value (“CNavave” + “CL2ave”) is calculated, so that the product “Ngate x CI x (“CNavave” + “CL2ave”)” is defined to be the second load capacity capacitor 6. As a result, the logic gate circuit part of the first power model of the first embodiment is prepared.

20

#### FIFTEENTH EMBODIMENT :

A fifteenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 17 is a flow chart illustrative of novel processes for modeling internal circuit

configurations of a ~~semiconductor~~ an integrated circuit into two stage gate circuits, wherein the novel processes are involved in a fifth novel method of designing a power model for an electro-magnetic interference simulation to a ~~semiconductor~~ an integrated circuit in a fifteenth embodiment in  
5 accordance with the present invention. All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S44, a total number “Ngate” of the all gate circuits included in the ~~semiconductor~~ integrated circuit is counted from all of the  
10 circuit configuration ~~informations~~ information stored in the data base. In second, third, fourth, fifth, sixth and seventh steps S45, S46, S47, S48, S49 and S50, on the basis of the ~~averaged~~ average values of the gate widths and gate ~~capacities~~ capacitances of the n-channel and p-channel transistors and the ~~averaged~~ average values of the interconnection ~~capacities~~ capacitances  
15 between the drains and the ~~powers~~ power terminals of the n-channel and p-channel transistors as well as an ~~averaged~~ average current value of the entire circuit configuration of the ~~semiconductor~~ integrated circuit and further an ~~averaged~~ average current value of a basic gate circuit prepared from the transistors and ~~capacities~~ capacitors having the above ~~averaged~~  
20 average values, all of the gate circuits in the operating state are modeled into a single gate circuit in order to prepare the above second power model described in the second embodiment in accordance with the present invention.

Namely, in the second step S45, an average current value “Iave”

of entire circuit configurations of the ~~semiconductor~~ integrated circuits is calculated from all of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit stored in the data base.

In the third step S46, the ~~averaged~~ average value “WPave” of  
5 gate widths “WPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the, p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL1ave” of  
10 interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fourth step S47, the ~~averaged~~ average value “WNavave” of  
gate widths “WNn” of all of the n-channel MOS field effect transistors  
15 included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CNavave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ~~averaged~~ average value “CL2ave” of  
interconnection ~~capacities~~ capacitances “CL2n” between drains and the  
20 second power terminal of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S48, basic gate circuits are prepared in respective correspondence with the actual gate circuits included in the ~~semiconductor~~ integrated circuits, wherein ~~informations~~ information about the actual gate

circuits are stored in the data base. The corresponding basic gate circuit is identical with the actual gate circuit in the circuit configurations, for example, the circuit elements and the number of the circuit elements and placements and interconnection relationships between the circuit elements.

5 However, the corresponding basic gate circuit is different from the actual gate circuit in the followings. All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate width "WPave". All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate  
10 ~~capacity~~ capacitance "CPave". All of the constitutional n-channel MOS field effect transistors of the basic gate circuit has the above ~~averaged~~ average gate width "WNave". All of the constitutional n-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate ~~capacity~~ capacitance "CNave". An average current value  
15 "IPRIave" of the above basic gate circuits in correspondence with the actual gate circuits included in the semiconductor device is calculated.

In the sixth step S49, a power current ratio "CI" is calculated, wherein the power current ratio "CI" is defined to be "IPRIave/Iave", or the ratio of the average current value "IPRIave" of the above basic gate circuits  
20 to the average current value "Iave" of the above actual gate circuits.

In the seventh step S50, the above logic gate circuit part of the above second novel power model shown in FIG. 4 is prepared. As described above, the logic gate circuit part of the above second novel power model comprises the first and second inverter circuits 19 and 24 and

a first pair of the first and second load ~~capacities~~ capacitors 22 and 23 and a second pair of the third and fourth load ~~capacities~~ capacitors 27 and 28. The first inverter circuit 19 further comprises a single pair of the p-channel MOS field effect transistor 20 and the n-channel MOS field effect transistor

5 21. The second inverter circuit 24 further comprises another single pair of the p-channel MOS field effect transistor 25 and the n-channel MOS field effect transistor 26. The product “Ngate x CI x WPave” of the total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the ~~averaged~~ average value “WPave” is calculated, so that a half “{Ngate x CI

10 x WPave}/2” of the product “Ngate x CI x WPave” is defined to be the gate width of each of the p-channel MOS field effect transistors 20 and 25. The product “Ngate x CI x WNav” of the total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the ~~averaged~~ average value “WNav” is calculated, so that a half “{Ngate x CI x WNav}/2” of

15 the product “Ngate x CI x WNav” is defined to be the gate width of each of the n-channel MOS field effect transistors 21 and 26. The product “Ngate x CI x (“CPave” + “CL1ave”)” of total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the ~~averaged~~ average value (“CPave” + “CL1ave”) is calculated, so that a half “{Ngate x CI x

20 (“CPave” + “CL1ave”)/2” of the product “Ngate x CI x (“CPave” + “CL1ave”)” is defined to be each of the first and third load ~~capacities~~ capacitors 22 and 27. The product “Ngate x CI x (“CNav” + “CL2ave”)” of total number “Ngate” of the all gate circuits, and the power current ratio “CI”, and the ~~averaged~~ average value (“CNav” + “CL2ave”) is calculated,

so that a half “ $\{N_{gate} \times C_I \times (C_{Nave} + C_{CL2ave})\}/2$ ” of the product  
“ $N_{gate} \times C_I \times (C_{Nave} + C_{CL2ave})$ ” is defined to be each of the second  
and fourth load ~~capacities~~ capacitors 23 and 28. As a result, the logic gate  
circuit part of the second power model of the second embodiment is  
5 prepared.

#### SIXTEENTH EMBODIMENT :

A sixteenth embodiment according to the present invention will  
be described in detail with reference to the drawings. FIG. 18 is a flow  
10 chart illustrative of novel processes for modeling internal circuit  
configurations of ~~a semiconductor~~ an integrated circuit into an equivalent  
internal capacitive part, wherein the novel processes are involved in the  
first novel method of designing a power model for an electro-magnetic  
interference simulation to ~~a semiconductor~~ an integrated circuit in a  
15 sixteenth embodiment in accordance with the present invention.

The above sixth embodiment in accordance with the present  
invention does provide the logic gate circuit part of the first power model  
shown in FIG. 3 described in the above first embodiment in accordance  
with the present invention. Namely, the logic gate circuit part of the first  
20 power model shown in FIG. 3 described in the above first embodiment is  
prepared in accordance with the novel processes shown in FIG. 8 described  
in the sixth embodiment. The remaining part, for example, the equivalent  
internal capacitive part of the first power model shown in FIG. 3 described  
in the above first embodiment is prepared in accordance with novel



processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above sixth embodiment with the hereinafter described novel processes of this embodiment completes the first novel method of designing the first power  
5 model shown in FIG. 3 described in the first embodiment.

The above seventh embodiment in accordance with the present invention does provide the logic gate circuit part of the second power model shown in FIG. 4 described in the above second embodiment in accordance with the present invention. Namely, the logic gate circuit part of  
10 the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with the novel processes shown in FIG. 9 described in the seventh embodiment. The remaining part, for example, the equivalent internal capacitive part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in  
15 accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above seventh embodiment with the hereinafter described novel processes of this embodiment completes the second novel method of designing the second power model shown in FIG. 4 described in the second  
20 embodiment.

All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S51, all of the gate circuits in a non-operating state in accordance with an operational frequency or a clock frequency are

extracted from the data base. In second, third and fourth steps S52, S53 and S54, the all of the gate circuits in the non-operating state are modeled into the equivalent internal capacitive part comprising the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 in the first and second embodiments in order to prepare the above first and second power models described in the first and second embodiments in accordance with the present invention.

Namely, in the second step S52, the number “k” of the p-channel MOS field effect transistors in the non-operating state is confirmed. The reciprocal of the sum of the individual reciprocals of the ON-resistances “RONPn” of all of the p-channel MOS field effect transistors in the non-operating state is calculated. The sum “CP” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the non-operating state is calculated. The sum “CL1” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is calculated.

In the third step S53, the number “k” of the n-channel MOS field effect transistors in the non-operating state is confirmed. The reciprocal of the sum of the individual reciprocals of the ON-resistances “RONNn” of all of the n-channel MOS field effect transistors in the non-operating state is calculated. The sum “CN” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the non-operating state is calculated. The sum “CL2” of interconnection ~~capacities~~ capacitances

“CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is calculated.

In the fourth step S54, the above equivalent internal capacitive part of each of the above first and second novel power models shown in FIGS. 3 and 4 is prepared. As described above, the above equivalent internal capacitive part of each of the above first and second novel power models comprises the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 described in the first and second embodiments. As described in the first and second embodiments, the logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state, even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The first equivalent internal capacitive element 9 corresponds to the

operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit. The product “2RONPn” of “2” and the ON-resistances “RONPn” of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the series resistance of the third equivalent internal capacitive element 11. The product “2RONNn” of “2” and the ON-resistances “RONNn” of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the series resistance of the second equivalent internal capacitive element 10. The arithmetic mean “(CP+CL1)/2” of the sum “CP” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the non-operating state and the sum “CL1” of interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the second equivalent internal ~~capacity~~ capacitor 10. The arithmetic mean “(CN+CL2)/2” of the sum “CN” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the non-operating state and the sum “CL2” of interconnection ~~capacities~~ capacitances “CL2n” between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the third equivalent internal ~~capacity~~ capacitor 11. The first equivalent internal ~~capacity~~ capacitor 9 is the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit and is previously decided in the design

process and independent from the operating and non-operating states, for which reason the first equivalent internal ~~capacity~~ capacitor 9 is not modeled. As a result, the equivalent internal capacitive part of each of the first and second power models of the first and second embodiments is  
5 prepared.

#### SEVENTEENTH EMBODIMENT :

A seventeenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 19 is a flow  
10 chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the second novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a  
15 seventeenth embodiment in accordance with the present invention.

The above eighth embodiment in accordance with the present invention does provide the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment in accordance with the present invention. Namely, the logic gate circuit part of the first  
20 power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with the novel processes shown in FIG. 10 described in the eighth embodiment. The remaining part, for example, the equivalent internal capacitive part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with

novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above eighth embodiment with the hereinafter described novel processes of this embodiment completes the second novel method of designing the first  
5 power model shown in FIG. 3 described in the first embodiment.

The above ninth embodiment in accordance with the present invention does provide the logic gate circuit part of the second power model shown in FIG. 4 described in the above second embodiment in accordance with the present invention. Namely, the logic gate circuit part of  
10 the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with the novel processes shown in FIG. 11 described in the ninth embodiment. The remaining part, for example, the equivalent internal capacitive part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in  
15 accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above ninth embodiment with the hereinafter described novel processes of this embodiment completes the second novel method of designing the second power model shown in FIG. 4 described in the second  
20 embodiment.

All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S55, all of the gate circuits in a non-operating state in accordance with an operational frequency or a clock frequency are

extracted from the data base and a total number “NgateNOP” of the gate circuits in the non-operating state is counted. In second, third and fourth steps S56, S57 and S58, the all of the gate circuits in the non-operating state are modeled into the equivalent internal capacitive part comprising the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 in the first and second embodiments in order to prepare the above first and second power models described in the first and second embodiments in accordance with the present invention.

Namely, in the second step S56, the ON-resistance average value  
10 RONPave of the ON-resistances “RONPn” of all of the p-channel MOS field effect transistors in the non-operating state is calculated. The gate ~~capacity~~ capacitance average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors in the non-operating state is calculated. The interconnection ~~capacity~~ capacitance  
15 average value “CL1ave” of the interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is calculated.

In the third step S57, the ON-resistance average value “RONNn” of the ON-resistances “RONNn” of all of the n-channel MOS field effect  
20 transistors in the non-operating state is calculated. The gate ~~capacity~~ capacitance average value “CNave” of gate ~~capacities~~ capacitances “CNn” of all of the n-channel MOS field effect transistors in the non-operating state is calculated. The interconnection ~~capacity~~ capacitance average value “CL2ave” of the interconnection ~~capacities~~ capacitances “CL2n” between

drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is calculated.

In the fourth step S58, the above equivalent internal capacitive part of each of the above first and second novel power models shown in  
5 FIGS. 3 and 4 is prepared. As described above, the above equivalent internal capacitive part of each of the above first and second novel power models comprises the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 described in the first and second embodiments. As described in the first and second embodiments,  
10 the logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state,  
15 even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant  
20 capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The first equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The



second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit. The “2RONPave/NgateNOP” is defined to be the series resistance of the third equivalent internal capacitive element 11. The  
5 “2RONNave/NgateNOP” is defined to be the series resistance of the second equivalent internal capacitive element 10. The product “NgateNOP  $\times$  (CPave+CL1ave)/2” of the total number “NgateNOP” of the logic gate circuits in the non-operating state and the arithmetic mean “(CPave+CL1ave)/2” of the average gate ~~capacities~~ capacitances “CPave”  
10 of all of the p-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances “CL1ave” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the second equivalent internal ~~capacity~~ capacitor 10. The product “NgateNOP  $\times$  (CNave+CL2ave)/2” of the total number “NgateNOP” of the logic gate  
15 circuits in the non-operating state and the arithmetic mean “(CNave+CL2ave)/2” of the average gate ~~capacities~~ capacitances “CNave” of all of the n-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances “CL2ave”  
20 between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the third equivalent internal ~~capacity~~ capacitor 11. The first equivalent internal ~~capacity~~ capacitor 9 is the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit and is previously decided in the design

process and independent from the operating and non-operating states, for which reason the first equivalent internal ~~capacity~~ capacitor 9 is not modeled. As a result, the equivalent internal capacitive part of each of the first and second power models of the first and second embodiments is prepared.

#### EIGHTEENTH EMBODIMENT :

An eighteenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 20 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the third novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in an eighteenth embodiment in accordance with the present invention.

The above tenth embodiment in accordance with the present invention does provide the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment in accordance with the present invention. Namely, the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with the novel processes shown in FIG. 12 described in the tenth embodiment. The remaining part, for example, the equivalent internal capacitive part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with

novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above tenth embodiment with the hereinafter described novel processes of this embodiment completes the third novel method of designing the first  
5 power model shown in FIG. 3 described in the first embodiment.

The above eleventh embodiment in accordance with the present invention does provide the logic gate circuit part of the second power model shown in FIG. 4 described in the above second embodiment in accordance with the present invention. Namely, the logic gate circuit part of  
10 the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with the novel processes shown in FIG. 13 described in the eleventh embodiment. The remaining part, for example, the equivalent internal capacitive part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in  
15 accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above eleventh embodiment with the hereinafter described novel processes of this embodiment completes the third novel method of designing the second power model shown in FIG. 4 described in the second  
20 embodiment.

All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S59, all of the gate circuits both in the operating and non-operating states in accordance with an operational frequency or a clock

frequency are extracted from the data base and a total number “Ngate” of the gate circuits included in the ~~semiconductor~~ integrated circuit is counted. In second, third, fourth, fifth and sixth steps S60, S61, S62, S63 and S64, the all of the gate circuits in the non-operating state are modeled into the equivalent internal capacitive part comprising the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 in the first and second embodiments in order to prepare the above first and second power models described in the first and second embodiments in accordance with the present invention.

10               Namely, in the second step S60, an average operational rate “ROPave” of the gate circuits is calculated, wherein the average operational rate is defined to be the ~~averaged~~ average value of the rate of the operating gate circuits in the operating state in accordance with an operational frequency or a clock frequency to the total gate circuits  
15 included in the ~~semiconductor~~ integrated circuit.

              In the third step S61, a total number “NgateNOP” of the gate circuits in the non-operating state is calculated, wherein the total number “NgateNOP” of the gate circuits in the non-operating state is defined to be the product “Ngate × (1 – ROPave)” of the total number “Ngate” of the  
20 gate circuits included in the ~~semiconductor~~ integrated circuit and the value “(1 – ROPave)”.

              In the fourth step S62, the ON-resistance average value “RONPave” of the ON-resistances “RONPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is

calculated. The gate ~~capacity~~ capacitance average value “CPave” of gate  
~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect  
transistors included in the ~~semiconductor~~ integrated circuit is calculated.  
The interconnection ~~capacity~~ capacitance average value “CL1ave” of the  
5 interconnection ~~capacities~~ capacitances “CL1n” between drains and the  
first power terminal of all of the p-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S63, the ON-resistance average value “RONNn”  
of the ON-resistances “RONNn” of all of the n-channel MOS field effect  
10 transistors included in the ~~semiconductor~~ integrated circuit is calculated.  
The gate ~~capacity~~ capacitance average value “CNave” of gate ~~capacities~~  
capacitances “CNn” of all of the n-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated. The  
interconnection ~~capacity~~ capacitance average value “CL2ave” of the  
15 interconnection ~~capacities~~ capacitances “CL2n” between drains and the  
second power terminal of all of the n-channel MOS field effect transistors  
included in the ~~semiconductor~~ integrated circuit is calculated.

In the sixth step S64, the above equivalent internal capacitive  
part of each of the above first and second novel power models shown in  
20 FIGS. 3 and 4 is prepared. As described above, the above equivalent  
internal capacitive part of each of the above first and second novel power  
models comprises the first, second and third equivalent internal ~~capacities~~  
capacitors 9, 10 and 11 shown in FIGS. 3 and 4 described in the first and  
second embodiments. As described in the first and second embodiments,

the logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state, even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The first equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit. The “ $2R_{ONPave}/N_{gateNOP}$ ” is defined to be the series resistance of the third equivalent internal capacitive element 11. The “ $2R_{ONNave}/N_{gateNOP}$ ” is defined to be the series resistance of the second equivalent internal capacitive element 10. The product “ $N_{gateNOP} \times (C_{Pave} + C_{L1ave})/2$ ” of the total number “ $N_{gateNOP}$ ” of the logic gate circuits in the non-operating state and the arithmetic mean “ $(C_{Pave} + C_{L1ave})/2$ ” of the average gate ~~capacities~~ capacitances “ $C_{Pave}$ ”

of all of the p-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances "CL1ave" between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the second  
5 equivalent internal ~~capacity~~ capacitor 10. The product " $\text{NgateNOP} \times (\text{CNave} + \text{CL2ave})/2$ " of the total number "NgateNOP" of the logic gate circuits in the non-operating state and the arithmetic mean " $(\text{CNave} + \text{CL2ave})/2$ " of the average gate ~~capacities~~ capacitances "CNave" of all of the n-channel MOS field effect transistors in the non-operating  
10 state and the average interconnection ~~capacities~~ capacitances "CL2ave" between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the third equivalent internal ~~capacity~~ capacitor 11. The first equivalent internal ~~capacity~~ capacitor 9 is the operating-irrelevant fixed part of the  
15 ~~semiconductor~~ integrated circuit and is previously decided in the design process and independent from the operating and non-operating states, for which reason the first equivalent internal capacity capacitor 9 is not modeled. As a result, the equivalent internal capacitive part of each of the first and second power models of the first and second embodiments is  
20 prepared.

#### NINETEENTH EMBODIMENT :

A nineteenth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 21 is a flow

chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the fourth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a nineteenth embodiment in accordance with the present invention.

The above twelfth embodiment in accordance with the present invention does provide the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment in accordance with the present invention. Namely, the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with the novel processes shown in FIG. 14 described in the twelfth embodiment. The remaining part, for example, the equivalent internal capacitive part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above twelfth embodiment with the hereinafter described novel processes of this embodiment completes the fourth novel method of designing the first power model shown in FIG. 3 described in the first embodiment.

The above thirteenth embodiment in accordance with the present invention does provide the logic gate circuit part of the second power model shown in FIG. 4 described in the above second embodiment in accordance with the present invention. Namely, the logic gate circuit part of



the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with the novel processes shown in FIG. 15 described in the thirteenth embodiment. The remaining part, for example, the equivalent internal capacitive part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above thirteenth embodiment with the hereinafter described novel processes of this embodiment completes the fourth novel method of designing the second power model shown in FIG. 4 described in the second embodiment.

All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S65, all of the gate circuits both in the operating and non-operating states in accordance with an operational frequency or a clock frequency are extracted from the data base and a total number "N<sub>gate</sub>" of the gate circuits included in the ~~semiconductor~~ integrated circuit is counted. In second, third, fourth, fifth and sixth steps S66, S67, S68, S69 and S70, the all of the gate circuits in the non-operating state are modeled into the equivalent internal capacitive part comprising the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 in the first and second embodiments in order to prepare the above first and second power models described in the first and second embodiments in accordance with the present invention.

Namely, in the second step S66, an maximum operational rate “ROPmax” of the gate circuits is calculated, wherein the maximum operational rate is defined to be the maximum value of the rate of the operating gate circuits in the operating state in accordance with an operational frequency or a clock frequency to the total gate circuits included in the ~~semiconductor~~ integrated circuit.

In the third step S67, a total number “NgateNOP” of the gate circuits in the non-operating state is calculated, wherein the total number “NgateNOP” of the gate circuits in the non-operating state is defined to be the product “Ngate  $\times$  (1 – ROPmax)” of the total number “Ngate” of the gate circuits included in the ~~semiconductor~~ integrated circuit and the value “(1 – ROPmax)”.

In the fourth step S68, the ON-resistance average value “RONPave” of the ON-resistances “RONPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The gate ~~capacity~~ capacitance average value “CPave” of gate ~~capacities~~ capacitances “CPn” of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The interconnection ~~capacity~~ capacitance average value “CLlave” of the interconnection ~~capacities~~ capacitances “CL1n” between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S69, the ON-resistance average value “RONNn” of the ON-resistances “RONNn” of all of the n-channel MOS field effect

transistors included in the ~~semiconductor~~ integrated circuit is calculated. The gate ~~capacity~~ capacitance average value "CNave" of gate ~~capacities~~ capacitances "CNn" of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The  
5 interconnection ~~capacity~~ capacitance average value "CL2ave" of the interconnection ~~capacities~~ capacitances "CL2n" between drains and the second power terminal of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the sixth step S70, the above equivalent internal capacitive  
10 part of each of the above first and second novel power models shown in FIGS. 3 and 4 is prepared. As described above, the above equivalent internal capacitive part of each of the above first and second novel power models comprises the first, second and third equivalent internal capacities  
capacitors 9, 10 and 11 shown in FIGS. 3 and 4 described in the first and  
15 second embodiments. As described in the first and second embodiments, the logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~  
20 integrated circuits, wherein the non-operating state parts are in the rest state, even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed

part of the ~~semiconductor~~ integrated circuit corresponds to a constant capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The first  
5 equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit. The “ $2R_{ONPave}/N_{gateNOP}$ ” is defined to be the series resistance  
10 of the third equivalent internal capacitive element 11. The “ $2R_{ONNave}/N_{gateNOP}$ ” is defined to be the series resistance of the second equivalent internal capacitive element 10. The product “ $N_{gateNOP} \times (C_{Pave} + CL_{1ave})/2$ ” of the total number “ $N_{gateNOP}$ ” of the logic gate circuits in the non-operating state and the arithmetic mean  
15 “ $(C_{Pave} + CL_{1ave})/2$ ” of the average gate ~~capacities~~ capacitances “ $C_{Pave}$ ” of all of the p-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances “ $CL_{1ave}$ ” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the second  
20 equivalent internal ~~capacity~~ capacitor 10. The product “ $N_{gateNOP} \times (C_{Nave} + CL_{2ave})/2$ ” of the total number “ $N_{gateNOP}$ ” of the logic gate circuits in the non-operating state and the arithmetic mean “ $(C_{Nave} + CL_{2ave})/2$ ” of the average gate ~~capacities~~ capacitances “ $C_{Nave}$ ” of all of the n-channel MOS field effect transistors in the non-operating

state and the average interconnection ~~capacities~~ capacitances "CL2ave" between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the third equivalent internal ~~capacity~~ capacitor 11. The first equivalent internal ~~capacity~~ capacitor 9 is the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit and is previously decided in the design process and independent from the operating and non-operating states, for which reason the first equivalent internal ~~capacity~~ capacitor 9 is not modeled. As a result, the equivalent internal capacitive part of each of the first and second power models of the first and second embodiments is prepared.

#### TWENTIETH EMBODIMENT :

A twentieth embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 22 is a flow chart illustrative of novel processes for modeling internal circuit configurations of ~~a semiconductor~~ an integrated circuit into an equivalent internal capacitive part, wherein the novel processes are involved in the fifth novel method of designing a power model for an electro-magnetic interference simulation to ~~a semiconductor~~ an integrated circuit in a twentieth embodiment in accordance with the present invention.

The above fourteenth embodiment in accordance with the present invention does provide the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment in accordance

with the present invention. Namely, the logic gate circuit part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with the novel processes shown in FIG. 16 described in the fourteenth embodiment. The remaining part, for example, 5 the equivalent internal capacitive part of the first power model shown in FIG. 3 described in the above first embodiment is prepared in accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above fourteenth embodiment with the hereinafter described novel 10 processes of this embodiment completes the fifth novel method of designing the first power model shown in FIG. 3 described in the first embodiment.

The above fifteenth embodiment in accordance with the present invention does provide the logic gate circuit part of the second power 15 model shown in FIG. 4 described in the above second embodiment in accordance with the present invention. Namely, the logic gate circuit part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with the novel processes shown in FIG. 17 described in the fifteenth embodiment. The remaining part, for 20 example, the equivalent internal capacitive part of the second power model shown in FIG. 4 described in the above second embodiment is prepared in accordance with novel processes to be hereinafter described in this embodiment. Accordingly, a combination of the above described novel processes of the above fifteenth embodiment with the hereinafter described

novel processes of this embodiment completes the fifth novel method of designing the second power model shown in FIG. 4 described in the second embodiment.

5 All of the circuit configuration ~~informations~~ information of the ~~semiconductor~~ integrated circuit are stored in a data base or a net list.

In a step S71, all of the gate circuits both in the operating and non-operating states in accordance with an operational frequency or a clock frequency are extracted from the data base and a total number “Ngate” of the gate circuits included in the ~~semiconductor~~ integrated circuit is counted.  
10 In second, third, fourth, fifth and sixth steps S72, S73, S74, S75 and S76, the all of the gate circuits in the non-operating state are modeled into the equivalent internal capacitive part comprising the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 in the first and second embodiments in order to prepare the above first  
15 and second power models described in the first and second embodiments in accordance with the present invention.

Namely, in the second step S72, an average current value “Iave” of entire circuit configurations of the ~~semiconductor~~ integrated circuits is calculated from all of the circuit configuration ~~informations~~ information of  
20 the ~~semiconductor~~ integrated circuit stored in the data base.

In the third step S73, a gate width average value “WPave” of the gate widths of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ON-resistance average value “RONPave” of the ON-resistances “RONPn” of all of the p-channel

MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The gate ~~capacity~~ capacitance average value "CPave" of gate ~~capacities~~ capacitances "CPn" of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is  
5 calculated. The interconnection ~~capacity~~ capacitance average value "CL1ave" of the interconnection ~~capacities~~ capacitances "CL1n" between drains and the first power terminal of all of the p-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S74, a gate width average value "WNAve" of the  
10 gate widths of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The ON-resistance average value "RONNn" of the ON-resistances "RONNn" of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The gate ~~capacity~~ capacitance average value "CNAve"  
15 of gate ~~capacities~~ capacitances "CNn" of all of the n-channel MOS field effect transistors included in the ~~semiconductor~~ integrated circuit is calculated. The interconnection ~~capacity~~ capacitance average value "CL2ave" of the interconnection ~~capacities~~ capacitances "CL2n" between drains and the second power terminal of all of the n-channel MOS field  
20 effect transistors included in the ~~semiconductor~~ integrated circuit is calculated.

In the fifth step S75, basic gate circuits are prepared in respective correspondence with the actual gate circuits included in the ~~semiconductor~~ integrated circuits, wherein ~~informations~~ information about the actual gate



circuits are stored in the data base. The corresponding basic gate circuit is identical with the actual gate circuit in the circuit configurations, for example, the circuit elements and the number of the circuit elements and placements and interconnection relationships between the circuit elements.

5 However, the corresponding basic gate circuit is different from the actual gate circuit in the followings. All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate width “WPave”. All of the constitutional p-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate  
10 ~~capacity~~ capacitance “CPave”. All of the constitutional n-channel MOS field effect transistors of the basic gate circuit has the above ~~averaged~~ average gate width “WNave”. All of the constitutional n-channel MOS field effect transistors of the basic gate circuit have the above ~~averaged~~ average gate ~~capacity~~ capacitance “CNave”. An average current value  
15 “IPRIave” of the above basic gate circuits in correspondence with the actual gate circuits included in the semiconductor device is calculated.

In the sixth step S76, a power current ratio “CI” is calculated, wherein the power current ratio is defined to be a ratio of the above ~~averaged~~ average current value “IPRIave” of all of the basic gate circuits to  
20 an ~~averaged~~ average current value “Iave” of all of the constituting gate circuits. A total number “NgateNOP” of the gate circuits in the non-operating state is calculated, wherein the total number “NgateNOP” of the gate circuits in the non-operating state is defined to be the product  
“Ngate × (1 – IPRIave/Iave)” of the total number “Ngate” of the gate

circuits included in the ~~semiconductor~~ integrated circuit and the power current ratio "IPRIave/Iave".

In the sixth step S77, the above equivalent internal capacitive part of each of the above first and second novel power models shown in  
5 FIGS. 3 and 4 is prepared. As described above, the above equivalent internal capacitive part of each of the above first and second novel power models comprises the first, second and third equivalent internal ~~capacities~~ capacitors 9, 10 and 11 shown in FIGS. 3 and 4 described in the first and second embodiments. As described in the first and second embodiments,  
10 the logic gate circuit having the inverter circuit represents operating state parts of the ~~semiconductor~~ integrated circuit in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part represents non-operating state parts of the ~~semiconductor~~ integrated circuits, wherein the non-operating state parts are in the rest state,  
15 even the non-operating state parts are potentially operable in accordance with the frequency-fixed signal such as the clock signal. The equivalent internal capacitive part also represents an operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit, wherein the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit corresponds to a constant  
20 capacitance value, and the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit is previously decided in the design process and independent from the operating and non-operating states. The first equivalent internal capacitive element 9 corresponds to the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit. The

second and third equivalent internal capacitive elements 10 and 11 correspond to the non-operating state parts of the ~~semiconductor~~ integrated circuit. The “2RONPave/NgateNOP” is defined to be the series resistance of the third equivalent internal capacitive element 11. The  
5 “2RONNave/NgateNOP” is defined to be the series resistance of the second equivalent internal capacitive element 10. The product “NgateNOP  $\times$  (CPave+CL1ave)/2” of the total number “NgateNOP” of the logic gate circuits in the non-operating state and the arithmetic mean “(CPave+CL1ave)/2” of the average gate ~~capacities~~ capacitances “CPave”  
10 of all of the p-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances “CL1ave” between drains and the first power terminal of all of the p-channel MOS field effect transistors in the non-operating state is defined to be the second equivalent internal ~~capacity~~ capacitor 10. The product “NgateNOP  $\times$  (CNave+CL2ave)/2” of the total number “NgateNOP” of the logic gate  
15 circuits in the non-operating state and the arithmetic mean “(CNave+CL2ave)/2” of the average gate ~~capacities~~ capacitances “CNave” of all of the n-channel MOS field effect transistors in the non-operating state and the average interconnection ~~capacities~~ capacitances “CL2ave”  
20 between drains and the second power terminal of all of the n-channel MOS field effect transistors in the non-operating state is defined to be the third equivalent internal ~~capacity~~ capacitor 11. The first equivalent internal ~~capacity~~ capacitor 9 is the operating-irrelevant fixed part of the ~~semiconductor~~ integrated circuit and is previously decided in the design

process and independent from the operating and non-operating states, for which reason the first equivalent internal ~~capacity~~ capacitor 9 is not modeled. As a result, the equivalent internal capacitive part of each of the first and second power models of the first and second embodiments is prepared.

#### TWENTY FIRST EMBODIMENT :

A twenty first embodiment according to the present invention will be described in detail with reference to the drawings. FIG. 23 is a block diagram illustrative of a support system for designing a power model in a twenty first embodiment according to the present invention. The support system is to realize the above described first and second novel power models of the first and second embodiments in accordance with the above described first, second, third, fourth and fifth novel power model design methods of the above sixth through twentieth embodiments.

The support system has the following elements. A data base 63 is provided for storing ~~informations~~ information of internal circuit configurations of the ~~semiconductor~~ integrated circuit, and if any the circuit board on which the ~~semiconductor~~ integrated circuit is mounted. A storage medium 67 is also provided for storing ~~informations~~ information 68 about power model circuit elements and interconnections between the circuit elements of the power model as well as for storing a computer program 69 for designing the power model. A processor 64 is provided which is connected to the data base 63 and the storage medium 65 for executing the

computer program 69 to prepare the power model. An output device 70 is provided which is connected to the processor 64 for outputting the power model prepared by the processor 64. The processor 64 further comprises a central processing unit 65 and a memory 66 connected to the central processing unit 65. The central processing unit 65 is connected to the data base 63 for receiving the circuit ~~informations~~ information stored therein. The central processing unit 65 is also connected to the storage medium 67 for receiving both the ~~informations~~ information 68 about the power model circuit elements and interconnections between the circuit elements of the power model as well as the computer program 69 for designing the power model. The central processing unit 65 executes the computer program 69 to prepare the power model. The central processing unit 65 is also connected to the output device 70 for enabling the output device 70 to output the power model. The power model may be either the first or second novel power models shown in FIGS. 3 and 4. The computer program 69 accords to the above described first, second, third, fourth and fifth novel power model design methods of the above sixth through twentieth embodiments. The storage medium 67 may be realized by any available mediums such as a magnetic disk, a semiconductor memory, and a CD-ROM. The data base 63 stores all of the ~~informations~~ information about the ~~semiconductor~~ integrated circuit. All of the necessary ~~informations~~ information for the novel power model are obtained from the output device 70. The computer program 69 includes both the first program for designing the logic gate circuit part of the power model and the second program for designing the

equivalent internal capacitive part, wherein the logic gate circuit part represents the operating parts of the ~~semiconductor~~ integrated circuits, whilst while the equivalent internal capacitive part represents the non-operating parts of the ~~semiconductor~~ integrated circuits. There is no  
5 limitation to the sequence in execution of the first and second programs. The first equivalent internal ~~capacity~~ capacitor 9 in the first and second power models shown in FIGS. 3 and 4 may be obtained from the ~~informations about~~ information about placement of the well regions but not from the circuit ~~informations~~ information of the ~~semiconductor~~ integrated  
10 circuit. The power model is ~~designed~~ designed for the electro-magnetic interference simulation to an electromagnetic field distribution over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted. For this reason, a simulation program may be included in the above computer program 69 for designing the power model or may be excluded therefrom  
15 so that the simulation program is stored in another storage medium of a simulator separately from the above supporting system. If the above computer program 69 includes the simulation program, then the computer program 69 includes a first simulation program for analysis to circuits to obtain a current distribution over a circuit board on which the  
20 ~~semiconductor~~ integrated circuit is mounted. The computer program 69 further includes a second simulation program for analysis to electromagnetic field to obtain a distribution of electromagnetic field over the circuit board on which the ~~semiconductor~~ integrated circuit is mounted.

FIG. 24 is a flow chart illustrative of the electromagnetic

interference simulation to the ~~semiconductor~~ integrated circuit by use of a simulator on the basis of the first and second novel power models shown in FIGS. 3 and 4 and prepared by the first, second, third, fourth and fifth design methods executed by the supporting system shown in FIG. 23. The  
5 simulator may comprise a circuit analyzing simulator 73 and an electromagnetic field analyzing simulator 75. The circuit analyzing simulator 73 is accessible to a first storage medium 71 for receiving a power model for a ~~semiconductor~~ an integrated circuit, and also being connected to a second storage medium 72 for receiving ~~informations~~  
10 information about a circuit board on which the ~~semiconductor~~ integrated circuit is mounted, so that the circuit analyzing simulator 73 analyzes the power model to obtain a current distribution 74 over a circuit board on which the ~~semiconductor~~ integrated circuit is mounted. The electromagnetic field analyzing simulator 75 is accessible to the circuit  
15 analyzing simulator 73 for receiving the current distribution 74, so that the electromagnetic field analyzing simulator 75 analyzes an electromagnetic field distribution 76 over the circuit board on which the ~~semiconductor~~ integrated circuit is mounted. The circuit analyzing simulator 73 may, for example comprise "Simulation Program with Integrated Circuit Emphasis  
20 (SPICE)". The above circuit analyzing simulator 73 and the electromagnetic field analyzing simulator 75 may be realized by a single package software such as "RADIA-WB PACKAGE" which is commercially available from Applied Simulation Technology. This package software has a circuit analyzing tool "ApsimSPICE" which corresponds to

the circuit analyzing simulator 73, and an electromagnetic field analyzing tool "RADIA" which corresponds to the electromagnetic field analyzing simulator 75.

FIG. 25 is a circuit diagram illustrative of a modeled circuit board connected to the novel power model for the electromagnetic interference simulation in accordance with the present invention. In accordance with the foregoing descriptions, the power model for the ~~semiconductor~~ integrated circuit has been described. Hereinafter, the power model for the circuit board on which the ~~semiconductor~~ integrated circuit will be described. The modeled circuit board has the following circuit elements. A de-coupling capacitor 55 is connected between the first ~~and~~ second powers power terminals. The de-coupling capacitor 55 further comprises a series connection of an equivalent series inductance 56, an equivalent ~~capacity~~ capacitor 57 and an equivalent series resistance 58. A power model 46 is also connected between the first and second ~~powers~~ power terminals 7 and 8. A first lead frame 47 and a first transmission line 53 are connected between the power model 46 and the first power terminal 7. The first lead frame 47 further comprises a series connection of a first lead frame inductance 48 and a first lead frame resistance 49. A second lead frame 50 and a second transmission line 54 are connected between the power model 46 and the second power terminal 8. The second lead frame 50 further comprises a series connection of a second lead frame inductance 51 and a second lead frame resistance 52. The de-coupling capacitor 55 contributes to suppress the electromagnetic interference. The above circuit



board model allows more accurate electromagnetic interference simulation.

FIG. 26 is a circuit diagram illustrative of a modeled ~~semiconductor~~ integrated circuit for the electromagnetic interference simulation in accordance with the present invention. The modeled ~~semiconductor~~ integrated circuit has the following circuit elements. A power model 46 is also connected between the first and second ~~powers~~ power terminals 7 and 8. A de-coupling capacitor 59 is connected between the first and second ~~powers~~ power terminals 7 and 8. The de-coupling capacitor 59 further comprises a series connection of an equivalent series inductance 60, an equivalent ~~capacity~~ capacitor 61 and an equivalent series resistance 62. The de-coupling capacitor 59 contributes to suppress the electromagnetic interference. The above ~~semiconductor~~ integrated circuit model allows more accurate electromagnetic interference simulation.

FIG. 27 is a diagram illustrative of variations in currents over frequency to show frequency spectrums which has been transformed by Fourier-transform from a current waveform which represents variation in current over time at a fixed point of a circuit board, wherein ● represents an actually measured value, ~~whilst~~ while ○ represents an analyzed value. The analysis was made by use of the design support system shown in FIG. 23 and the simulator shown in FIG. 24. The actual measurement was made by use of a magnetic probe positioned at the same point as the analysis. From FIG. 27, it is understood that the analyzed values are close to the actually measured value and the above novel power model of the present invention is usable in the light of the accuracy in the analysis.

Whereas modifications of the present invention will be apparent to a person having ordinary skill in the art, to which the invention pertains, it is to be understood that embodiments as shown and described by way of illustrations are by no means intended to be considered in a limiting sense.

- 5 Accordingly, it is to be intended to cover by claims all modifications which fall within the spirit and scope of the present invention.